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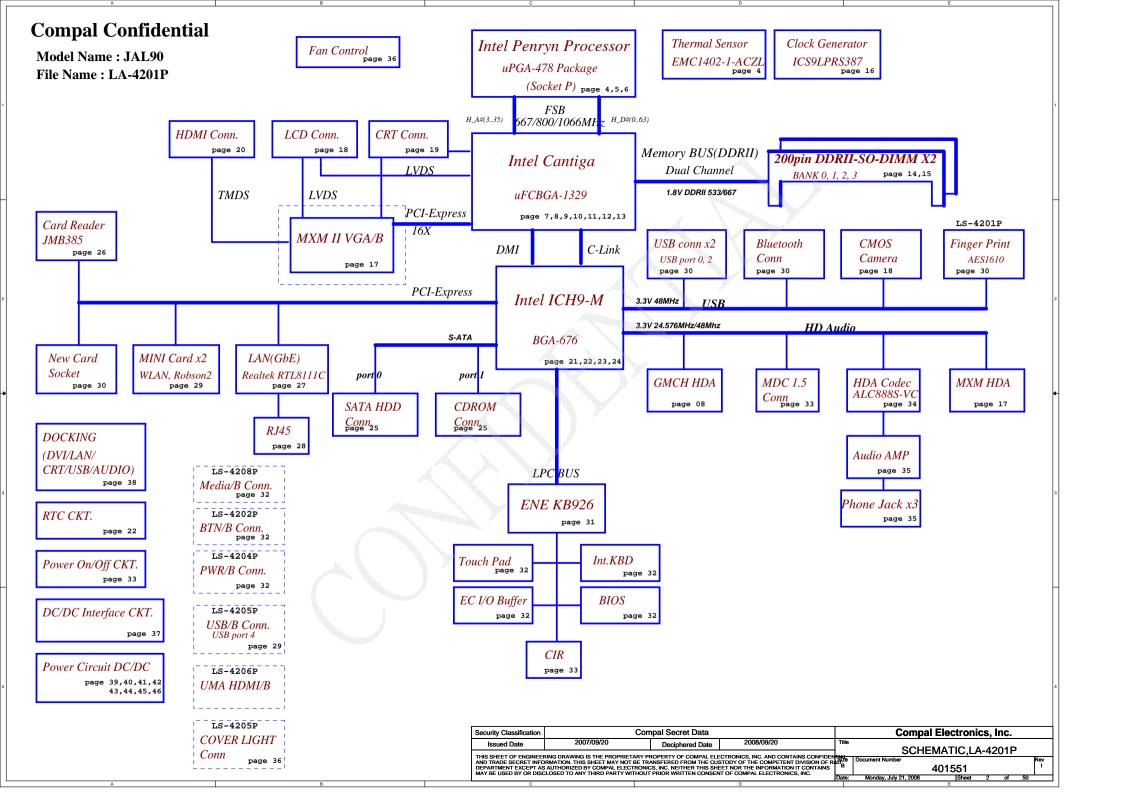
JAL90 M/B Schematics Document

Intel Penryn Processor with Cantiga + DDRII + ICH9M

2008-07-04

REV:1.0

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Voltage Rails

Power Plane	Description	S1	S 3	S5
VIN	Adapter power supply (19V)	N/A	N/A	N/A
B+	AC or battery power rail for power circuit.	N/A	N/A	N/A
+CPU_CORE	Core voltage for CPU	ON	OFF	OFF
+0.9VS	0.9V switched power rail for DDR terminator	ON	OFF	OFF
+1.05VS	1.05V switched power rail	ON	OFF	OFF
+1.25VS	1.25V switched power rail	ON	OFF	OFF
+1.5V	1.5V power rail for HDA	ON	ON	OFF
+1.5VS	1.5V switched power rail	ON	OFF	OFF
+1.8V	1.8V power rail for DDR	ON	ON	OFF
+1.8VS	1.8V switched power rail	ON	OFF	OFF
+2.5VS	2.5V switched power rail	ON	OFF	OFF
+3VALW	3.3V always on power rail	ON	ON	ON*
+3V	3.3V power rail for SB	ON	ON	Х
+3V_LAN	3.3V power rail for LAN	ON	ON	Х
+3VS	3.3V switched power rail	ON	OFF	OFF
+5VALW	5V always on power rail	ON	ON	ON*
+5VS	5V switched power rail	ON	OFF	OFF
+VSB	VSB always on power rail	ON	ON	ON*
+RTCVCC	RTC power	ON	ON	ON

Note: ON* means that this power plane is ON only with AC power available, otherwise it is OFF

External PCI Devices

Device	IDSEL#	REQ#/GNT#	Interrupts	

EC SM Bus1 address

EC SM Bus2 address

Device	Address	Device	Address
Smart Battery	0001 011X b	ADI ADT7421	1001 100X b
EEPROM(24C16/02)	1010 000X b		
GMT G781-1	1001 101X b		

ICH9M SM Bus address

Device	Address
Clock Generator (ICS9LPRS387, SLG8SP556V)	1101 001Xb
DDR DIMM0	1001 000Xb
DDR DIMM2	1001 010Xb

STATE	SLP_S1#	SLP_S3#	SLP_S4#	SLP_S5#	+VALW	+V	+VS	Clock
Full ON	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	ON
S1(Power On Suspend)	LOW	HIGH	HIGH	HIGH	ON	ON	ON	LOW
S3 (Suspend to RAM)	LOW	LOW	HIGH	HIGH	ON	ON	OFF	OFF
S4 (Suspend to Disk)	LOW	LOW	LOW	HIGH	ON	OFF	OFF	OFF
S5 (Soft OFF)	LOW	LOW	LOW	LOW	ON	OFF	OFF	OFF

Board ID / SKU ID Table for AD channel

Board ID Rh	100K +/- 5%			
0	100K +/- 5%			
_	b / Rd / Rf	V _{AD_BID} min	V _{AD_BID} typ	V _{AD_BID} max
1 8	0	0 V	0 V	0.155 V
	8.2K +/- 5%	0.168 V	0.250 V	0.362 V
2 1	18K +/- 5%	0.375 V	0.503 V	0.621 V
3 3	33K +/- 5%	0.634 V	0.819 V	0.945 V
4 5	56K +/- 5%	0.958 V	1.185 V	1.359 V
5 1	100K +/- 5%	1.372 V	1.650 V	1.838 V
6 2	200K +/- 5%	1.851 V	2.200 V	2.420 V
7	NC	2.433 V	3.300 V	3.300 V

BOARD ID Table

0.1
0.2
0.3
1.0
1A

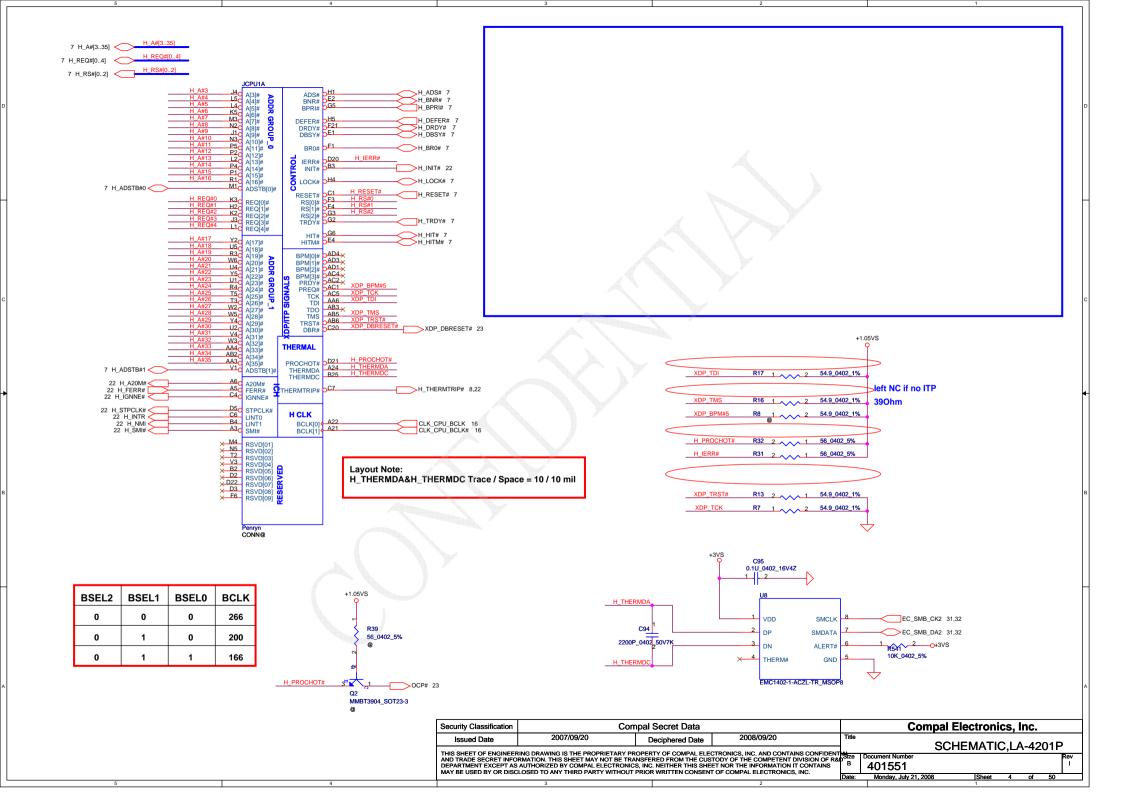
BTO Option Table

BTO Item	BOM Structure
JAL90	JAL90@
JAW50/KAW00	JAW50@
UMA	GM@
JAL90-UMA	JAL90GM@
JAW50/KAW00	GLPM@
Discrete	GLPMW
Discrete	PM@
ALC888VC	888VC@
ALC888VB	888VB@
8111C	8111C@
8102E	8102E@
ALC268	268@
JAL90/JAW50	ABO@
KAW00	EM@
JAL90/JAW50	JAL9050@
KAW00	0713020@
JAL90-DIS	JAL90PM@
JAW50-DIS	JAW50PM@
JAW50-UMA	JAW50GL@

BOM Configuration Table

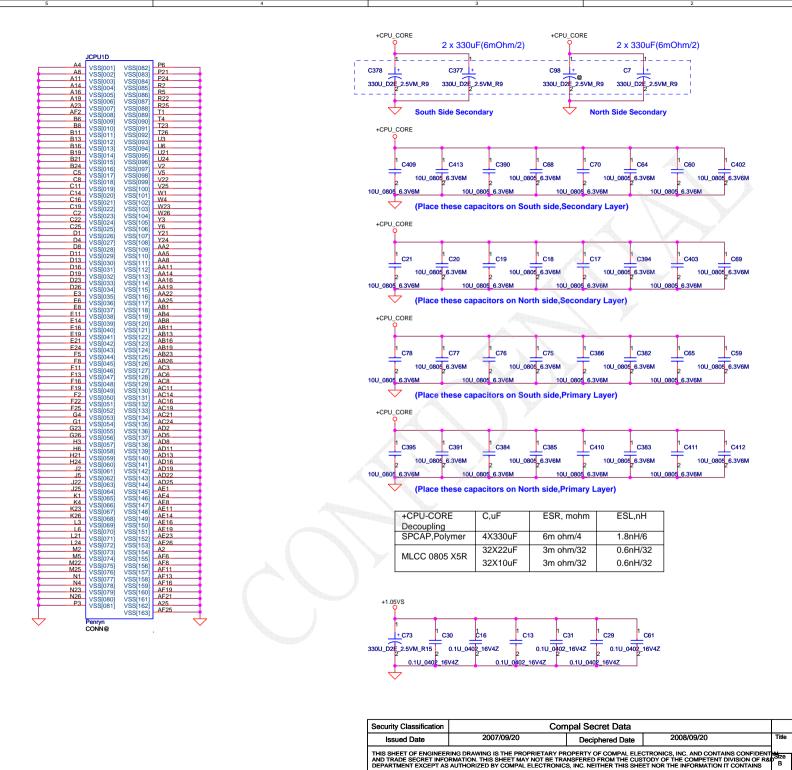
Project	BOM Configuration
JAL90-UMA	431551BOL01:JAL90GM@/JAL9050@/JAL90@/GM@/888VC@/8111C@/ABO@
JAL90-Dis	431551BOL02:PM@/JAL90PM@/JAL9050@/JAL90@/GLPM@/888VC@/8111C@/ABO@
JAW50-UMA	431551BOL11:JAW50@/JAW50GL@/JAL9050@/GM@/GLPM@/8111C@/268@/ABO@
JAW50-DIS	431551BOL12:PM@/JAW50@/JAW50PM@/JAL9050@/GLPM@/8111C@/268@/ABO@
KAW00	431551BOL31:JAW50@/JAW50GL@/JAL9050@/GM@/GLPM@/8111C@/268@/EM@

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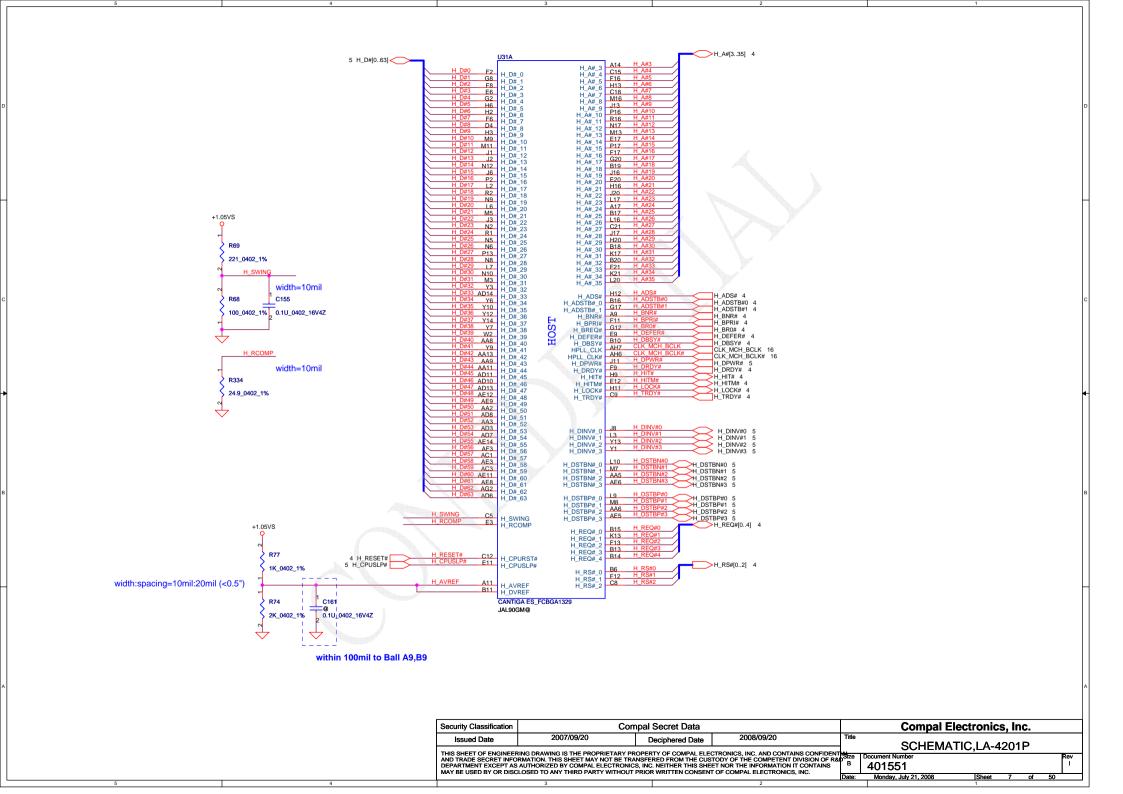
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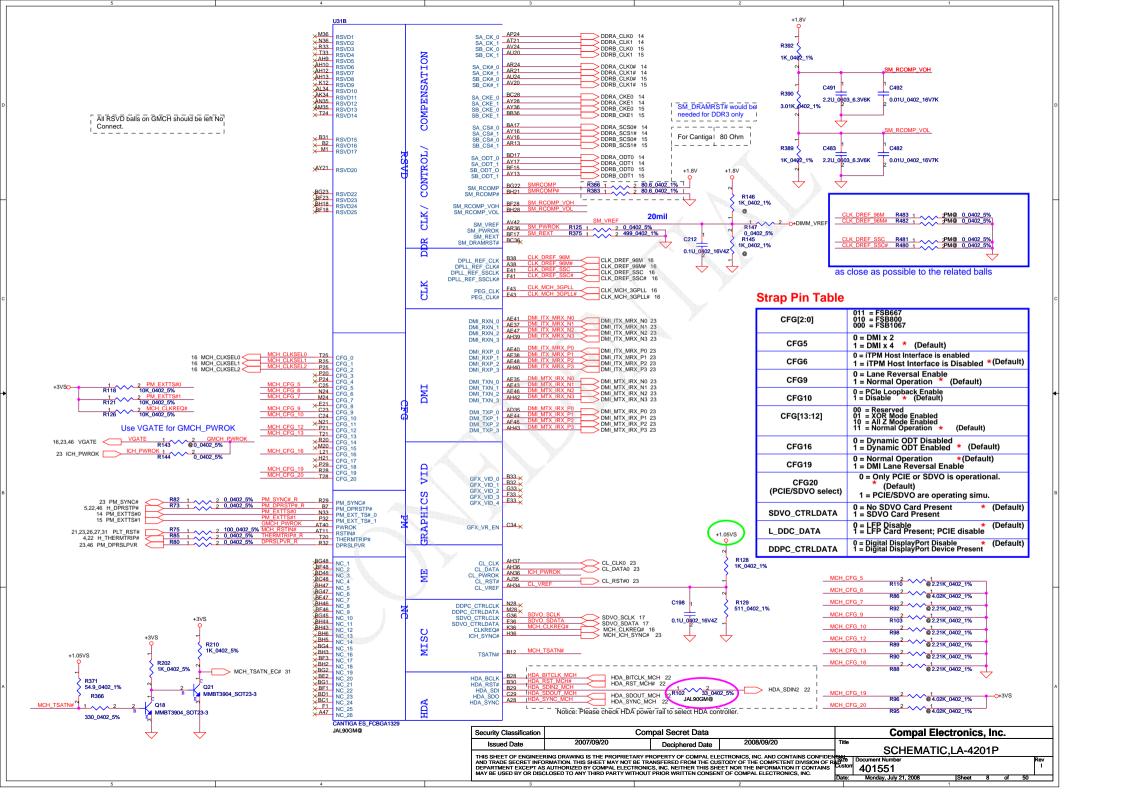
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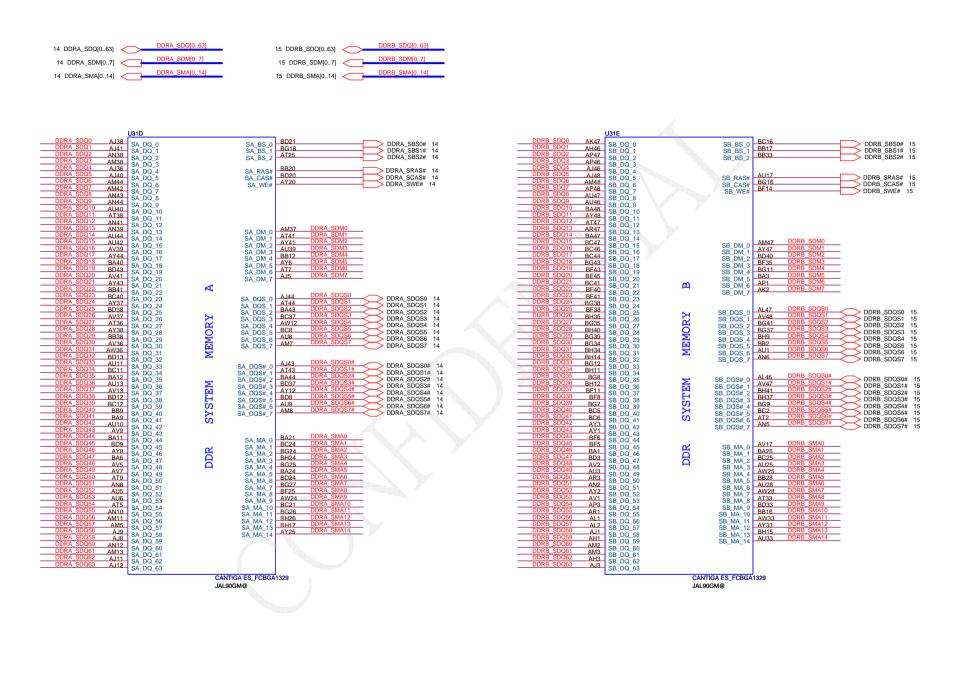
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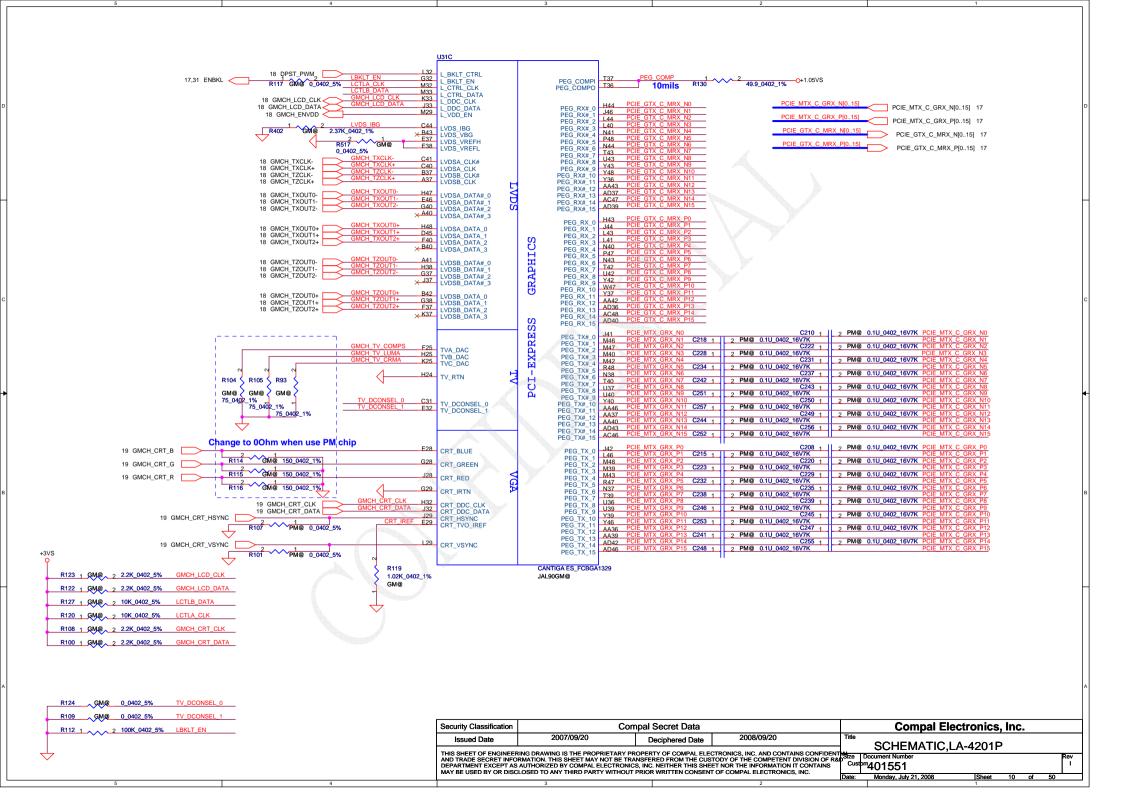
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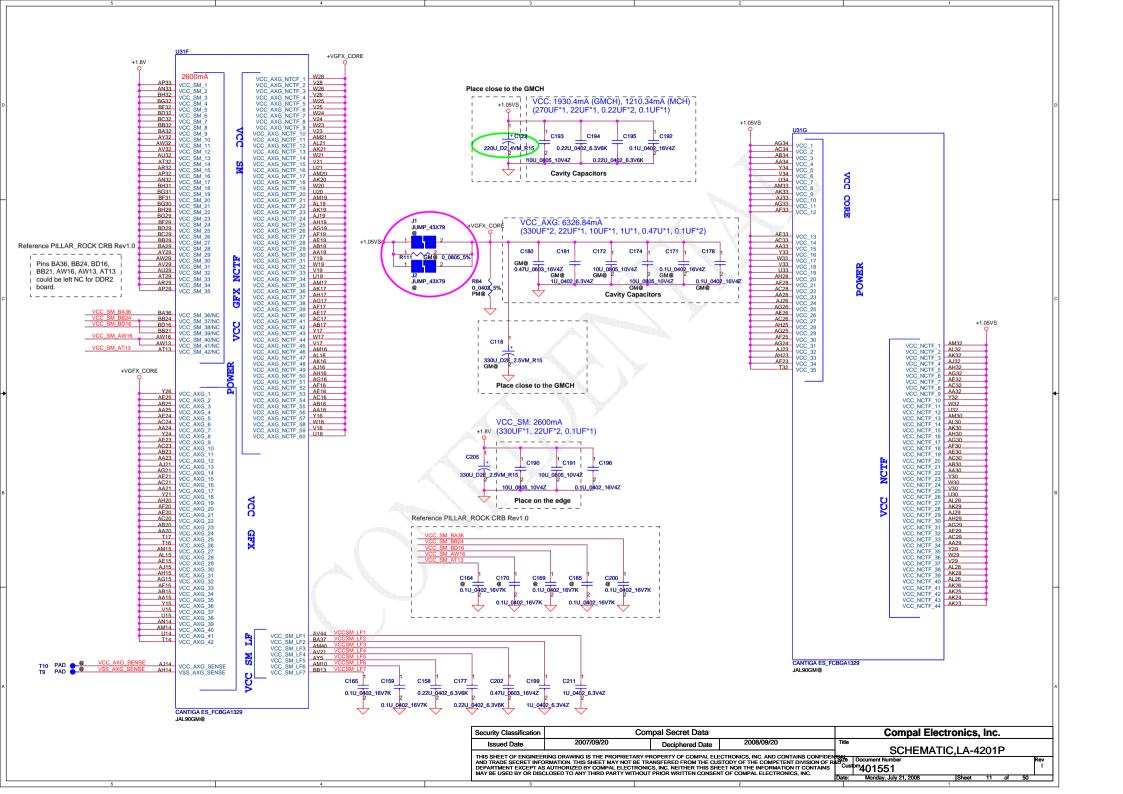


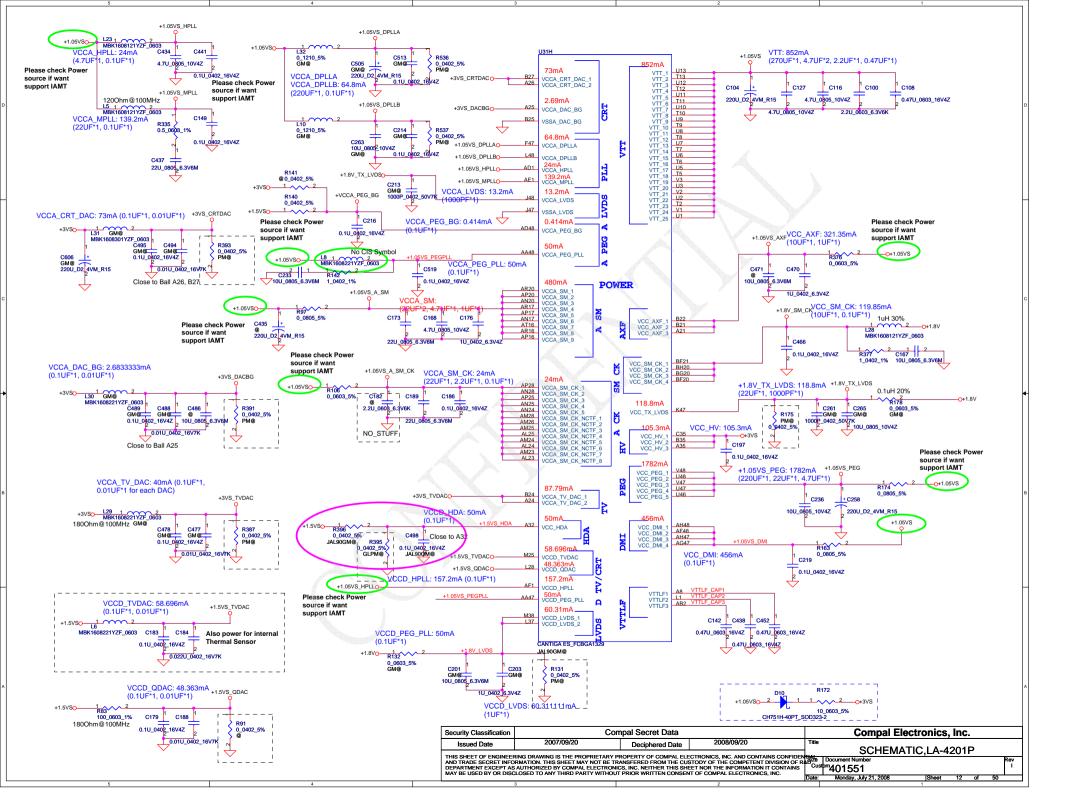


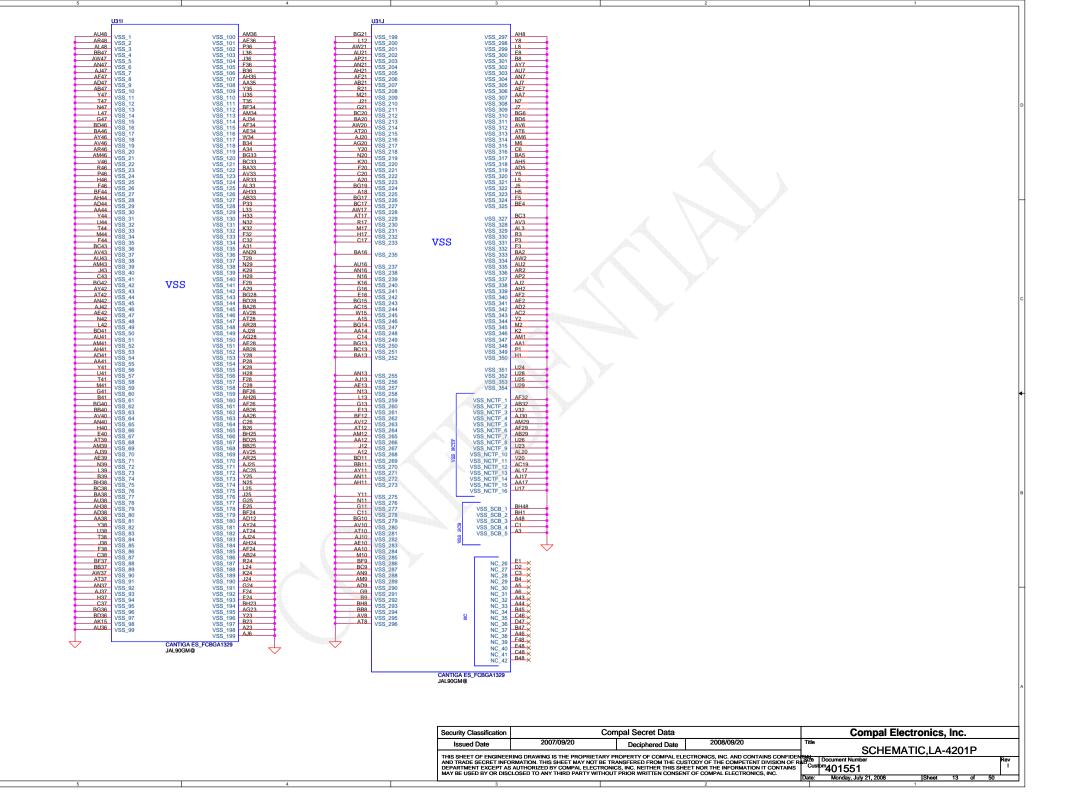


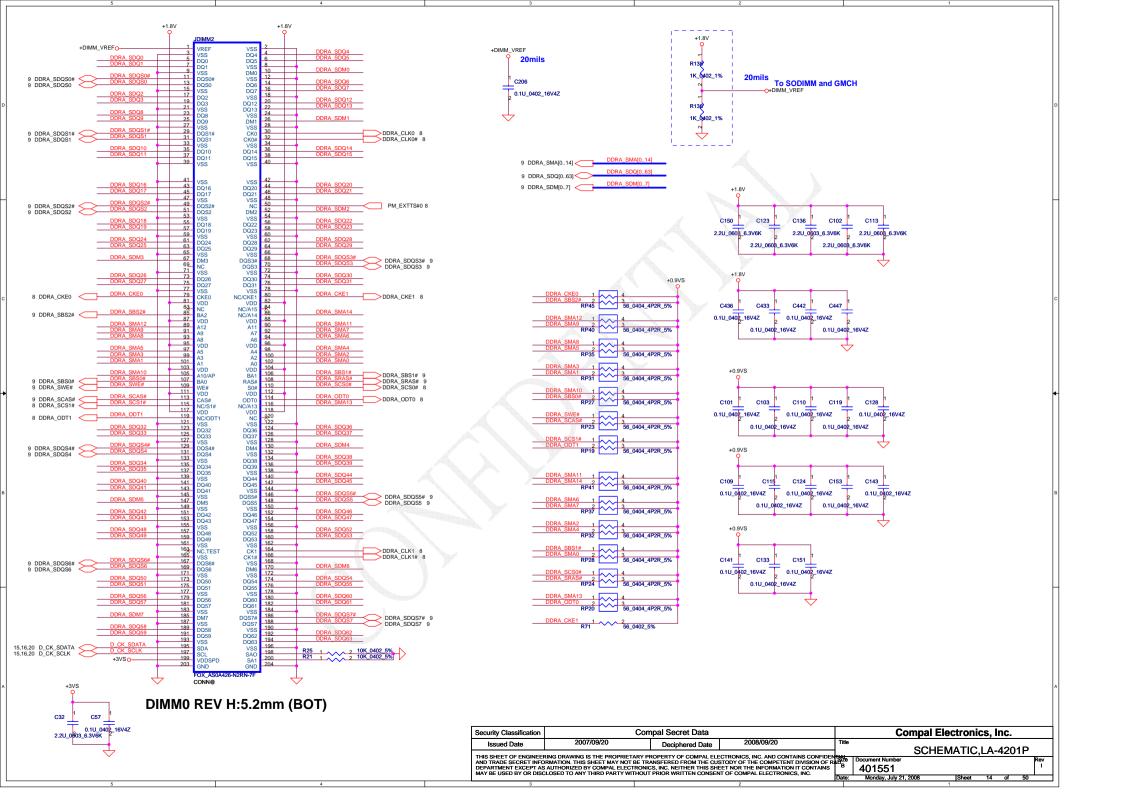
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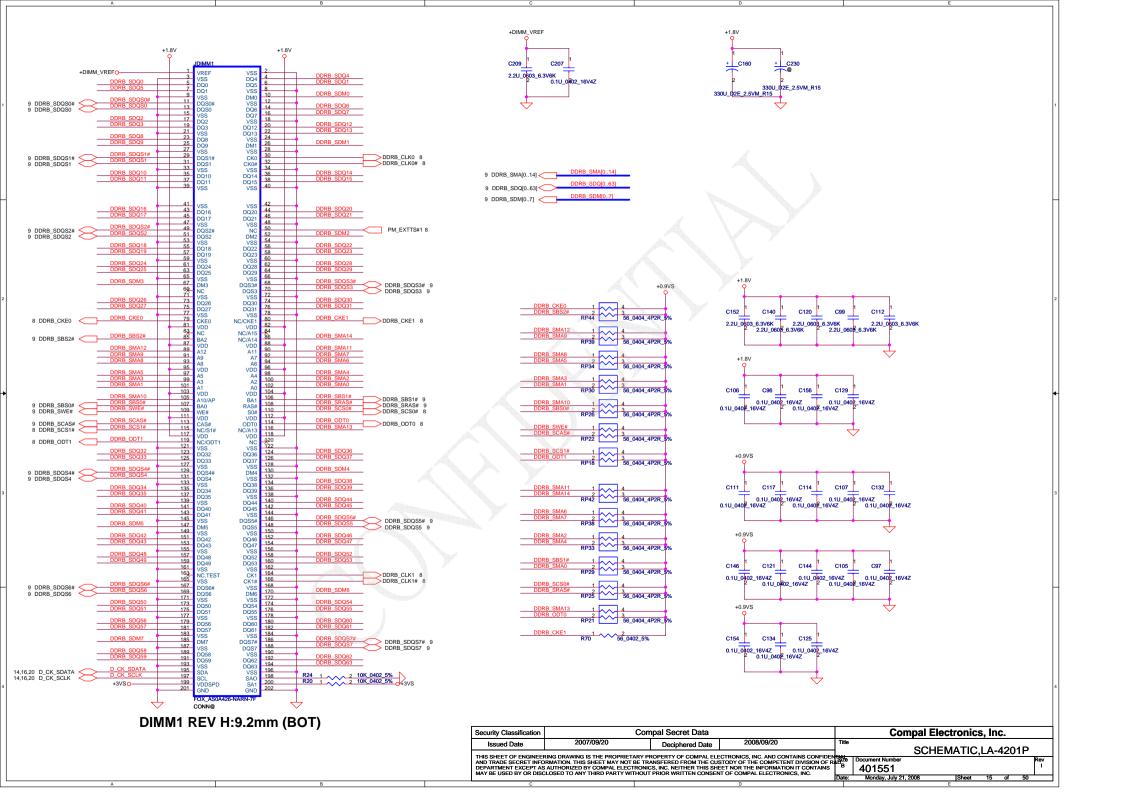


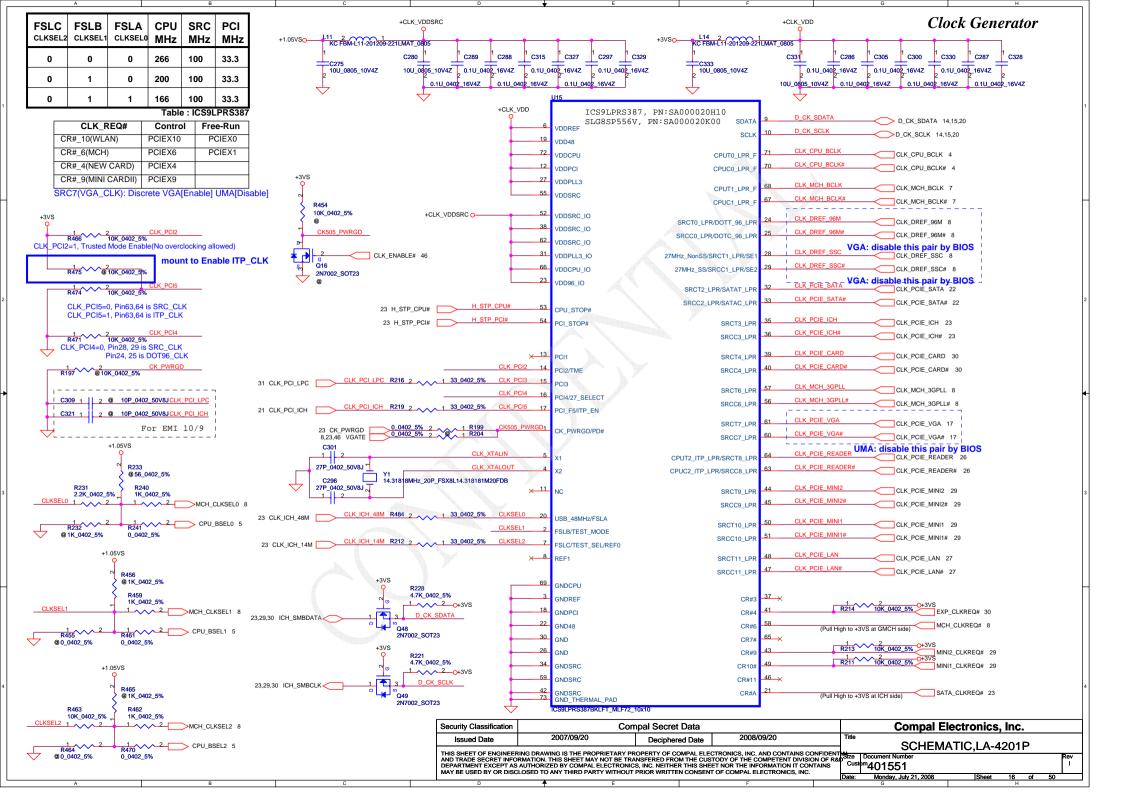


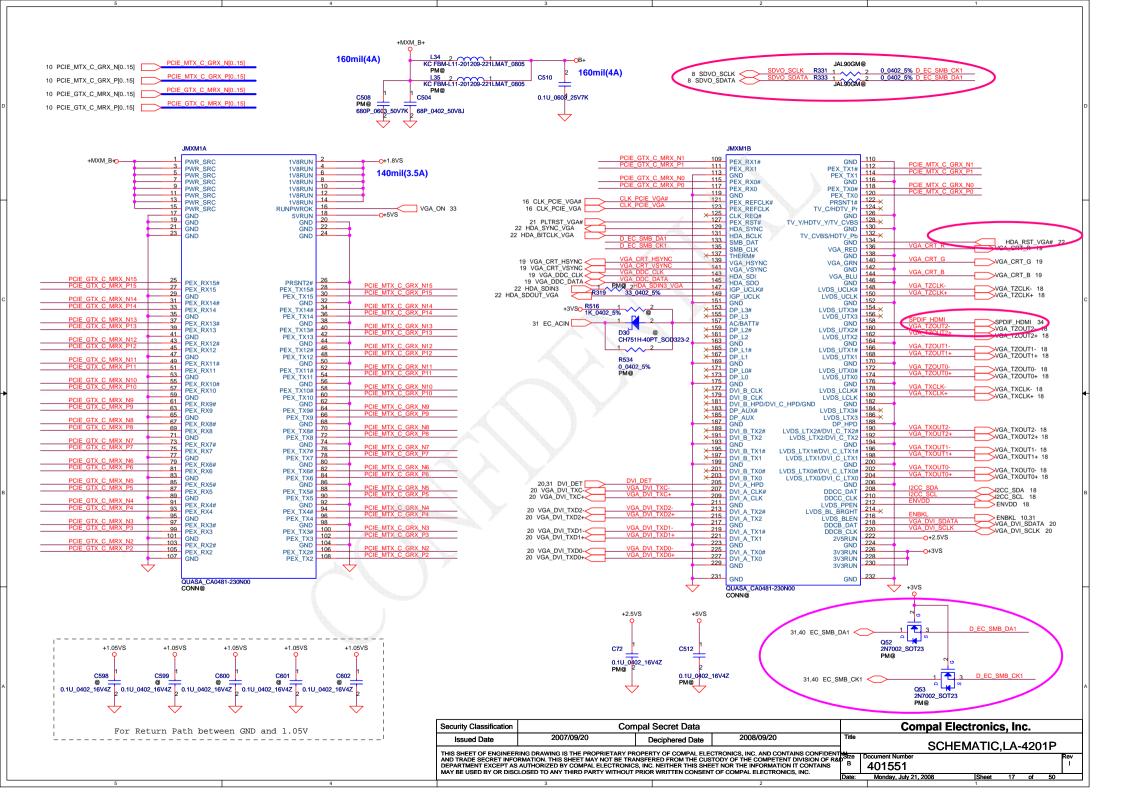


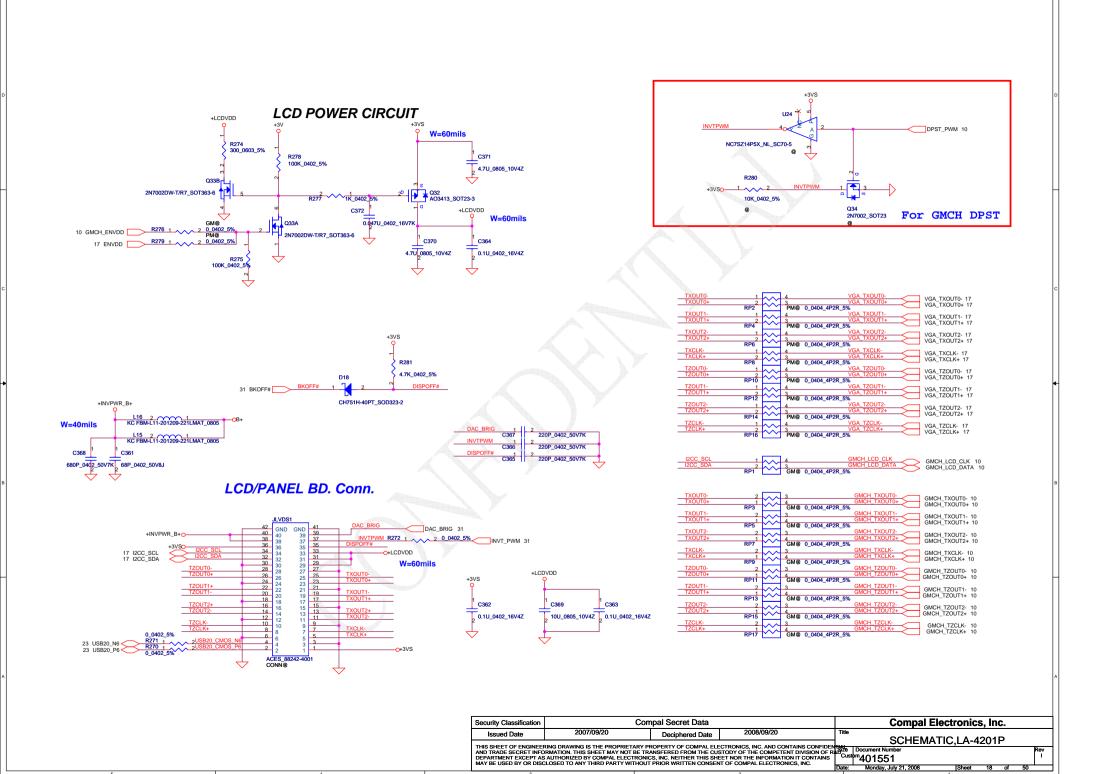


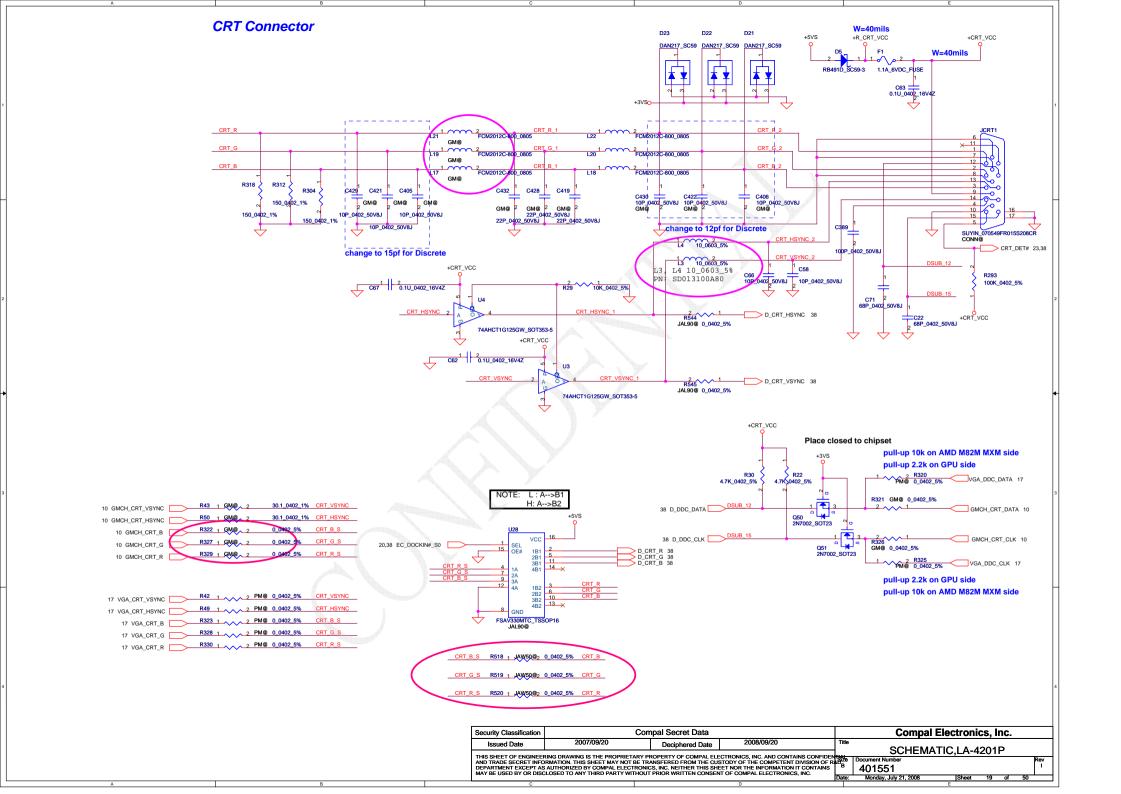


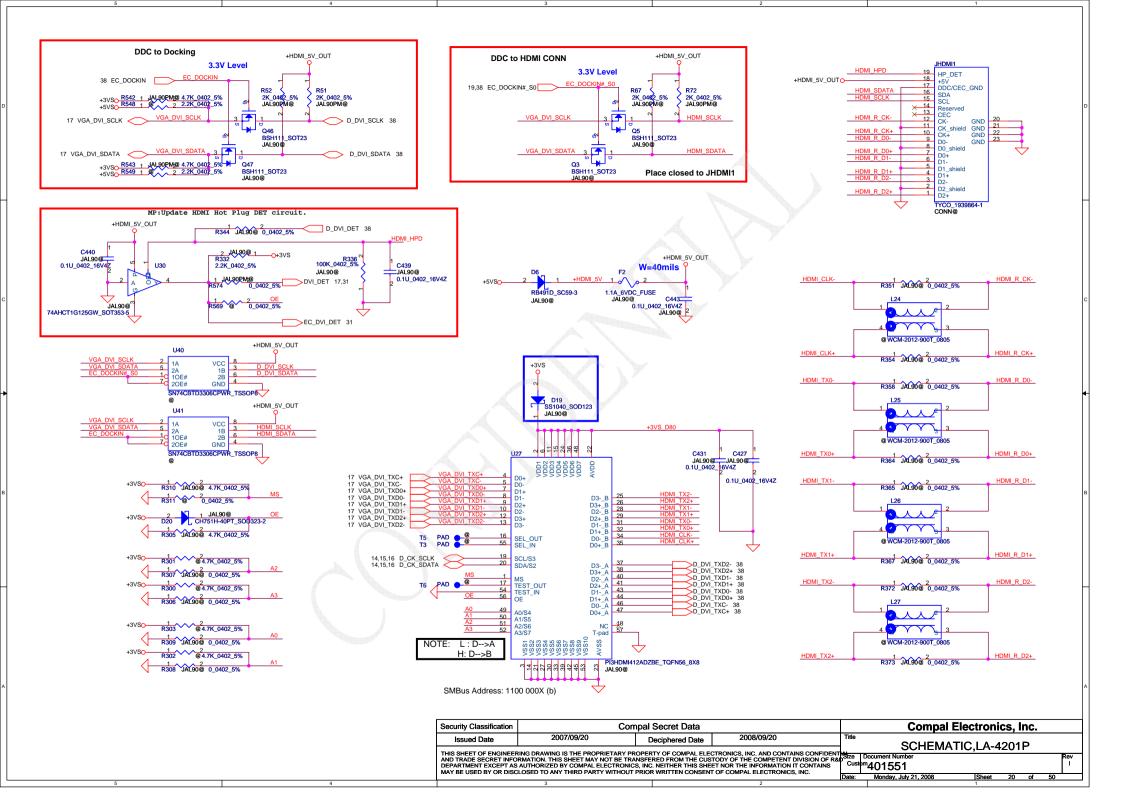


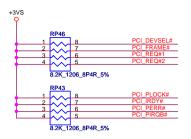


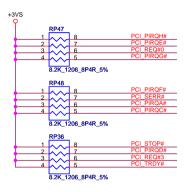












A16	Swap Override Strap
PCI_GNT#3	Low= A16 swap override Enable High= Default*

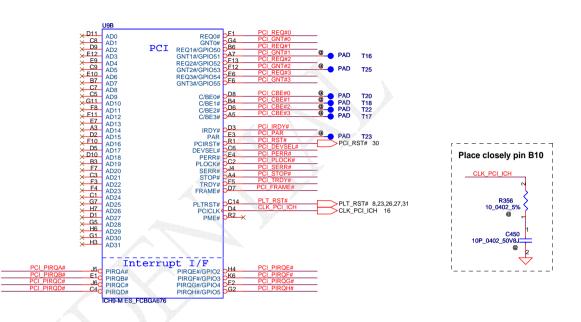
R345 1 2 1K_0402_5% PCL_GNT#3

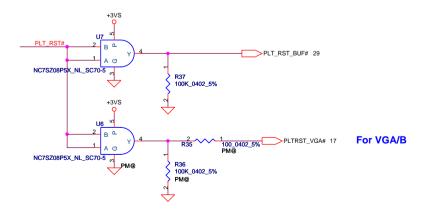
Boot BIOS Strap								
PCI_GNT#0	SPI_CS#1	Boot BIOS Loaction						
0	1	SPI						
1	0	PCI						
1	1	LPC*						



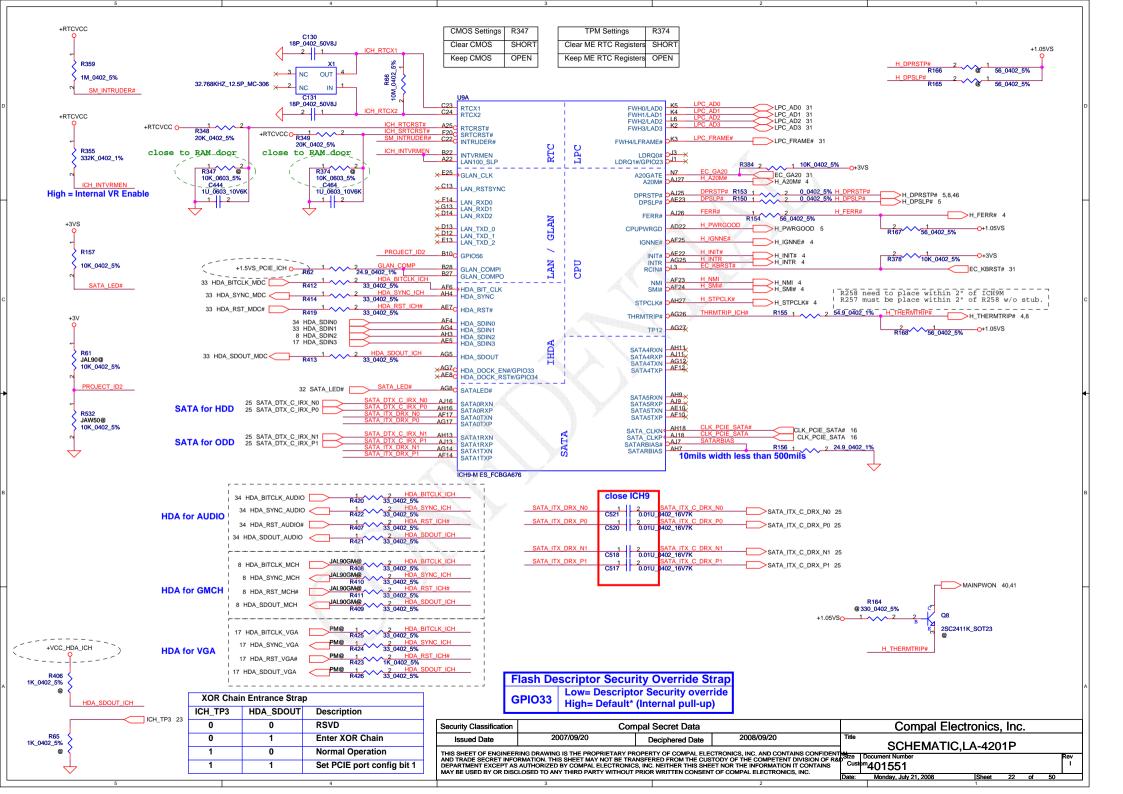
DMI for ESI-compatible operation

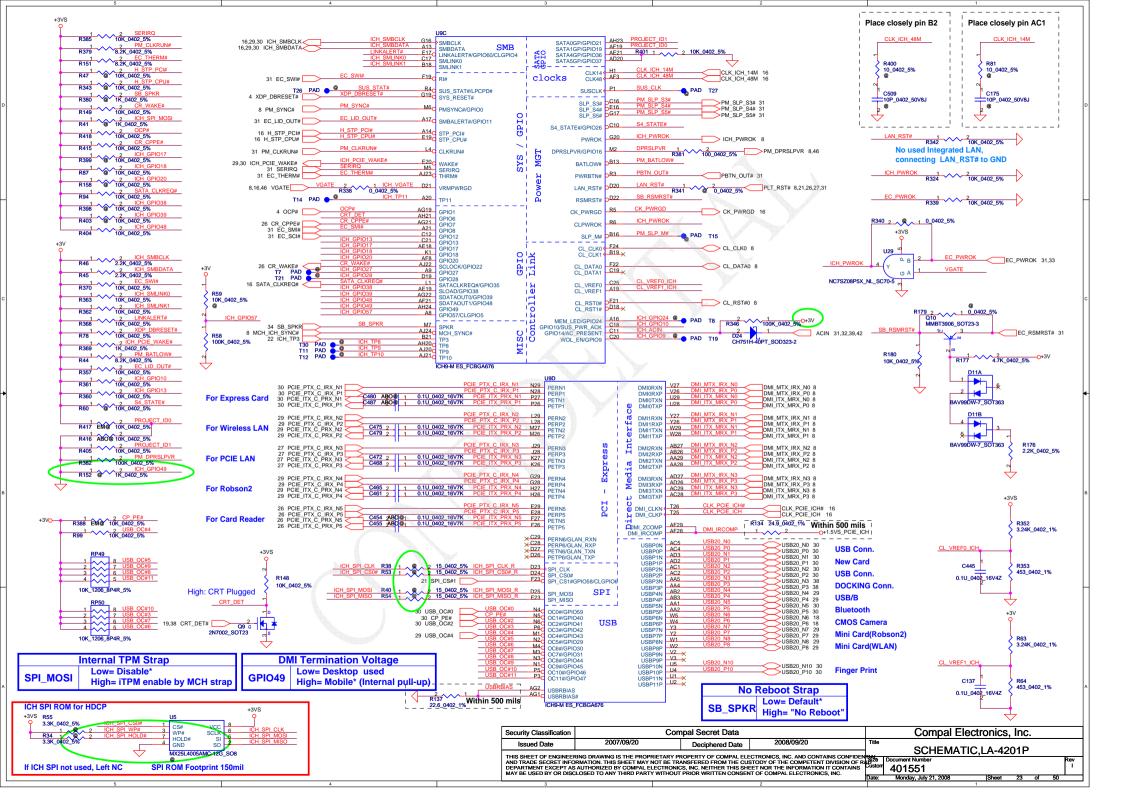
| Comparison | Low = DMI for ESI-compatible operation | High= Default* (Internal pull-up)

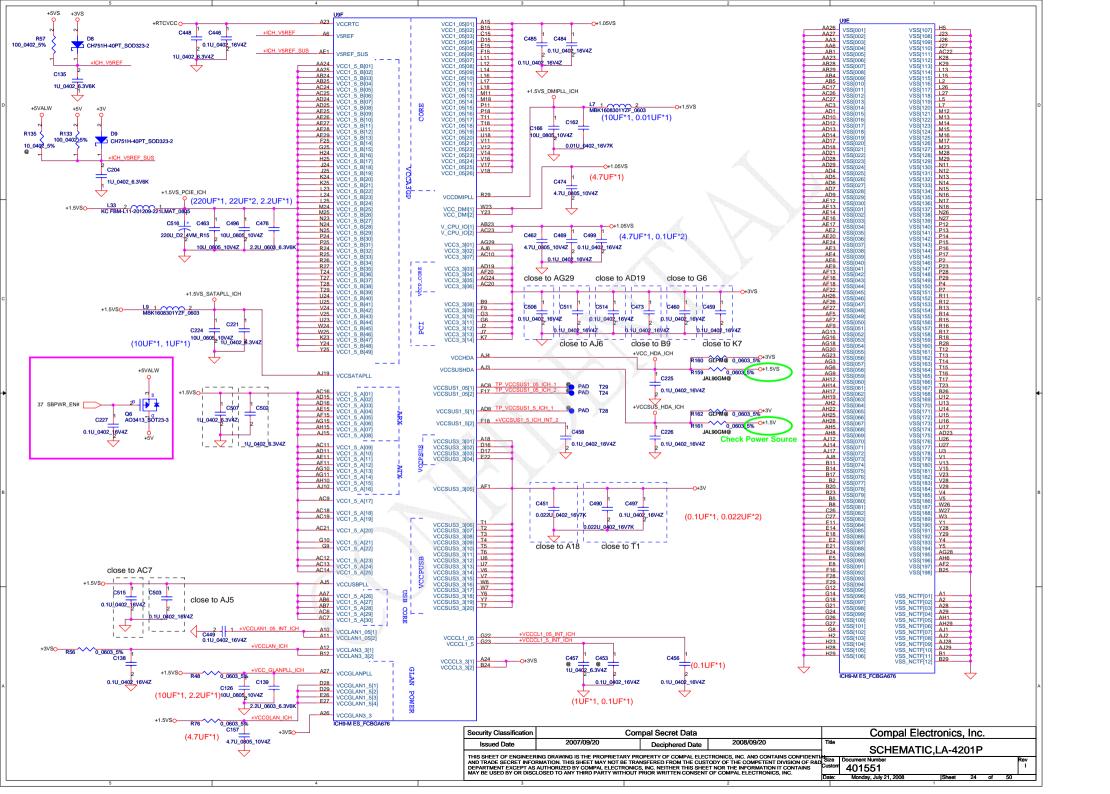


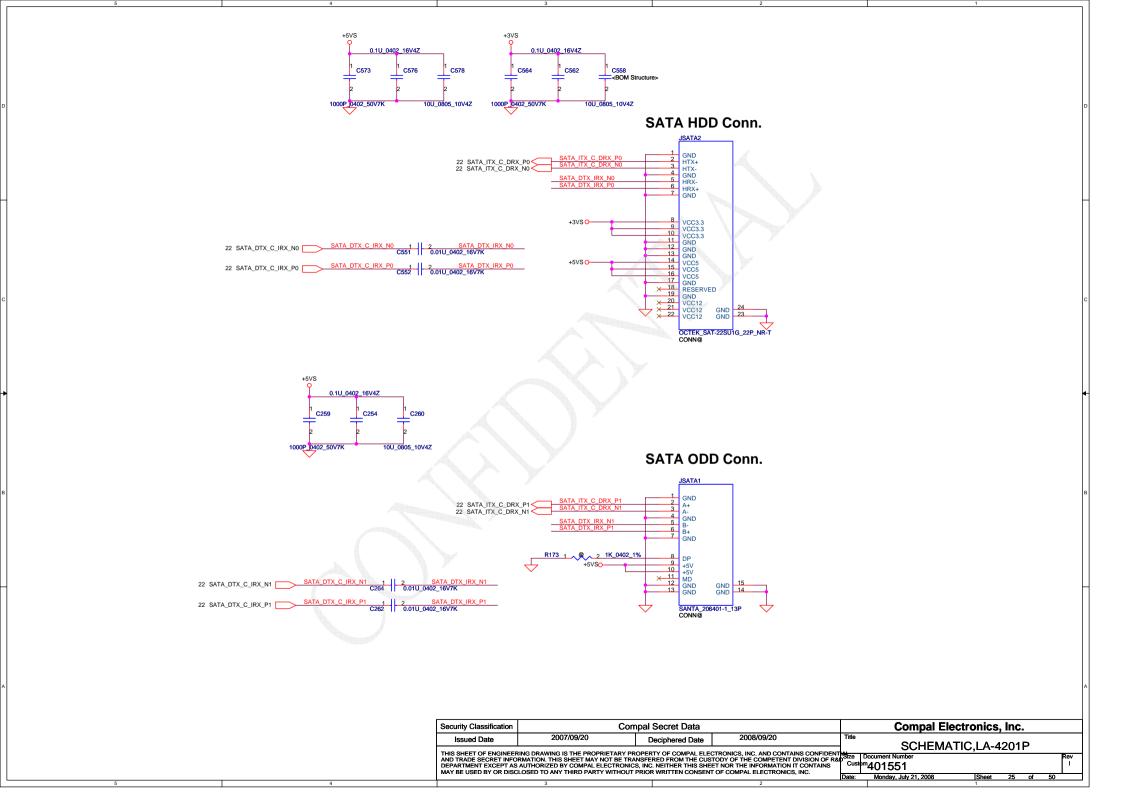


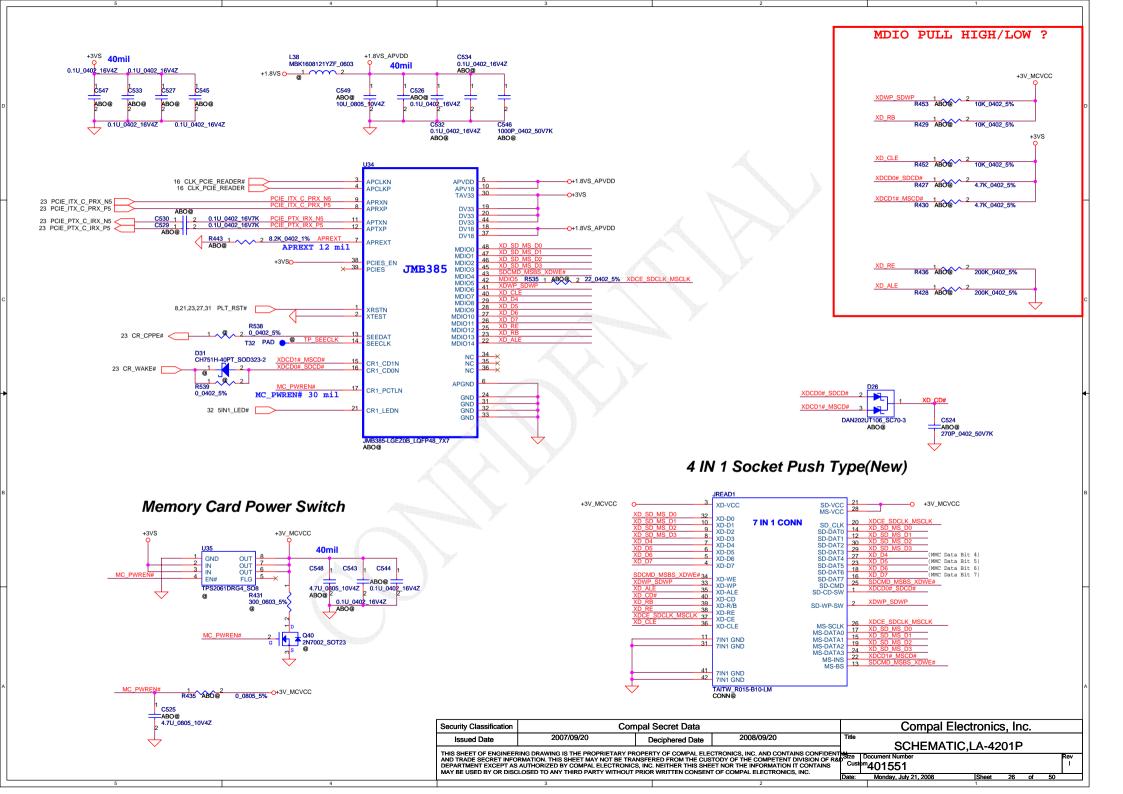
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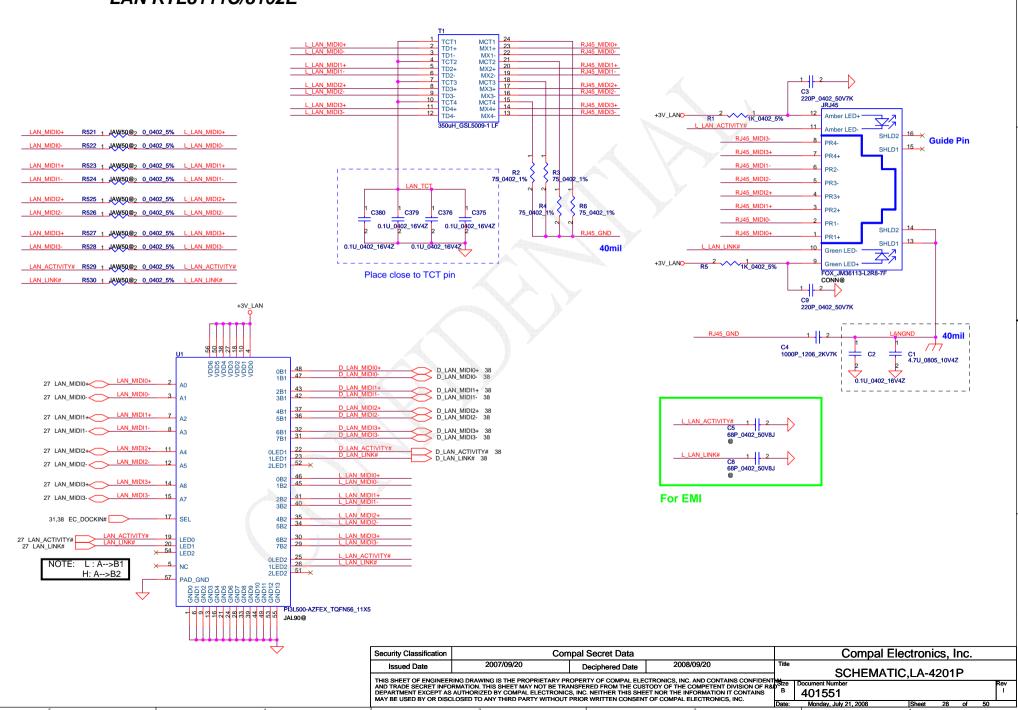


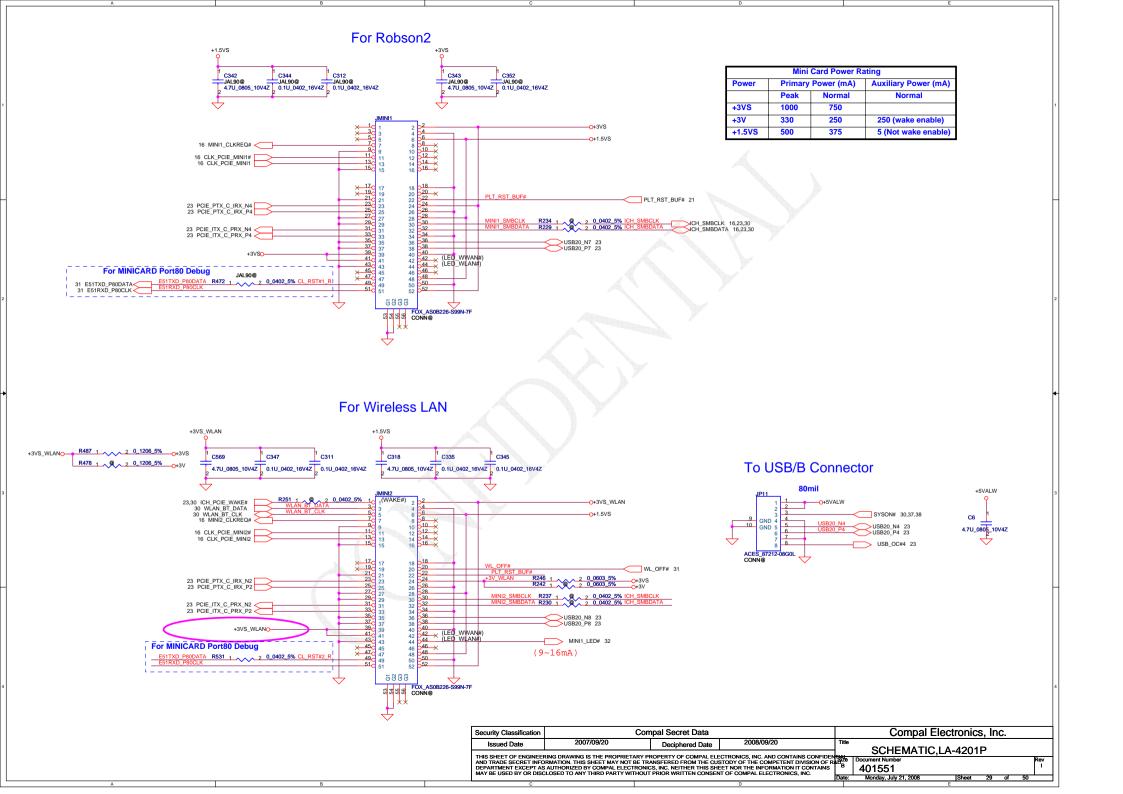




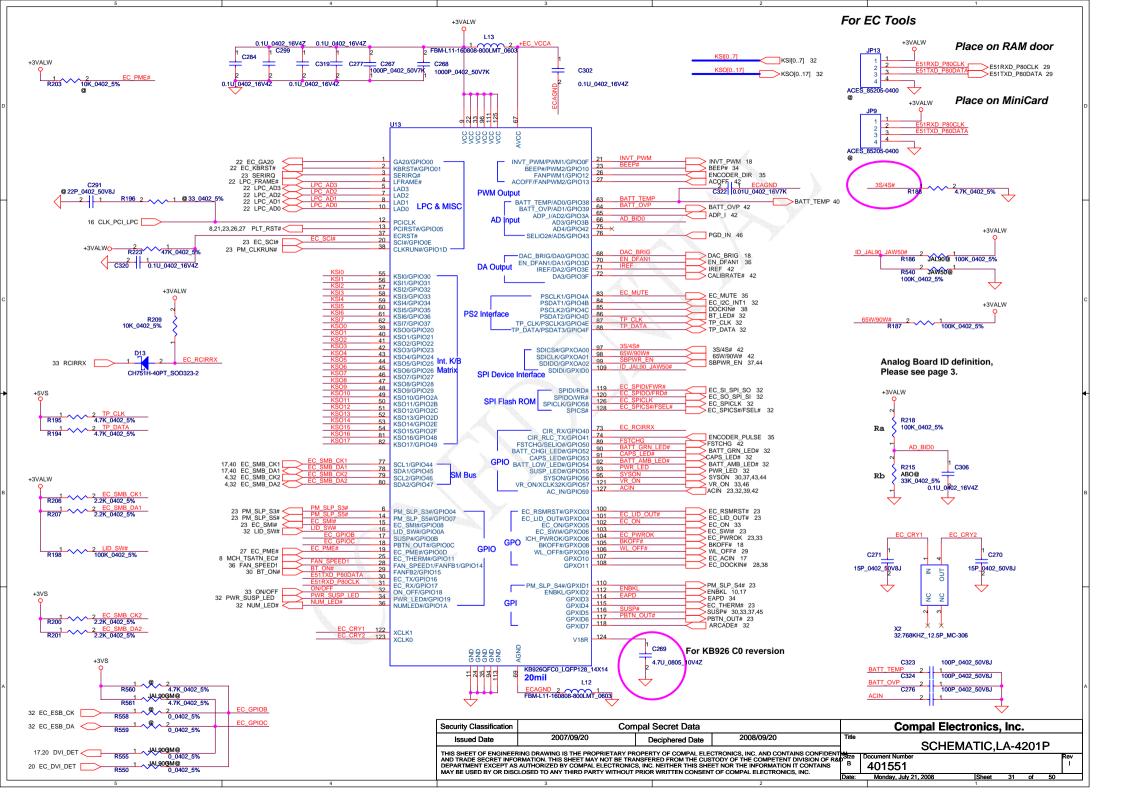
LAN RTL8111C/8102E Bead for 8111C 300mA 4.7uH choke L1 8111C@ 4.7UH 1008HC-472EJFS-A 5% 1008 +LAN AVDD18 L2 MBK1608121YZF_0603 **20mil** +1.8V I AN 60mil 40mil +3VALWO 1 0_1206_5% 40mil C426 C423 C408 C11 C12 C14 C24 C25 C26 C27 C401 1 C407 0.1U_0402_16V4Z 0.1U_0402_16V4Z 8102E@ 0_0805_5% 10U_0805_10V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V42 10U_0805_10V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z +3V I AN R23 0_0805_5% 8111C@ 0_0603_5% 8111C@ +1.2V_LAN 40mil 40mil C392 1 8111C@ = 0.1U_0402_16V4Z C15 =8111C@ 10U_0805_10V4Z 8102E@ C404 C418 C388 C398 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 0.1U_0402_16V4Z 2 R296 1 LAN_PME# +3V_LANO--100K_0402_5% Place closed to Chip C415 1 2 0.1U_0402_16V7K 23 PCIE PTX C IRX P3 EEDO EEDI/AUX C416 1 2 0.1U_0402_16V7K HSON FESK 23 PCIE_ITX_C_PRX_P3 HSIP 24 HSIN 23 PCIE_ITX_C_PRX_N3 54 × 55 × 56 57 LED3 LED2 R315 3.6K_0402_5% × 33 CLKREQB LED1 LED0 I AN LINK# 28 -O+3V LAN 16 CLK_PCIE_LAN REFCLK_P 16 CLK_PCIE_LAN# LAN_MIDI0+ 28 LAN_MIDI0- 28 LAN_MIDI1+ 28 REFCLK_N GND 6 × NC 7 × VCC 8 MDIN0 C420 @ =0.1U_0402_16V4Z DO PERSTR MDIP1 7 9 I AN MIDI1- 28 > LAN_MIDI2+ 28 > LAN_MIDI2- 28 __+3\/ I ΔN SROUT12 MDIN2 AT93C46-10SI-2.7_SO8 MDIP3 LAN MIDI3+ 28 +I AN AVDD180-FB12 LAN MIDI3- 28 +3V_LANO___R292_1_8111C@2_0_0603_5% ENSR -0+1.2V I AN DVDD12 R294 1 2 2.49K_0402_1% DVDD12 38 DVDD12 DVDD12 DVDD12 DVDD12 31 EC_PME# R298 1 2 0 0402 5% LAN_PME# LANWAKEB ISOLATEE ISOLATEB 0+1.8V LAN EVDD12 LAN_X1 CKTAL1 R314 1K_0402_1% LAN_X2 CKTAL2 O+3V LAN 37 VDD33 ISOLATEB EXPOSE_PAD VDDSR R313 15K_0402_1% +3V LAN +AVDD33 AVDD33 31 EGND AVDD33 R15 0_0805_5% O+LAN_AVDD18 AVDD12 +1.2V_LANO 15 NC × 17 NC × 18 NC × 34 NC × 35 NC × 39 NC × 40 NC × 41 NC × 42 NC AVDD12 AVDD12 AVDD12 O+1.2V_LAN +AVDD33 IGPIO 50 X C28 25MHZ_20P C400 27P_0402_50V8J 0.1U_0402_16V4Z 0.1U_0402_16V4Z RTL8111C-GR_QFN64_9X9 Place closed to Pin2 & Pin59 Compal Electronics, Inc. Security Classification Compal Secret Data 2007/09/20 2008/09/20 Issued Date Deciphered Date SCHEMATIC, LA-4201P THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENCY. AND TRADE SECKET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPETENT DIVISION OF REID DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WITHTEN CONSENT OF COMPAL ELECTRONICS, INC. 401551 Monday, July 21, 2008 Sheet 27 of

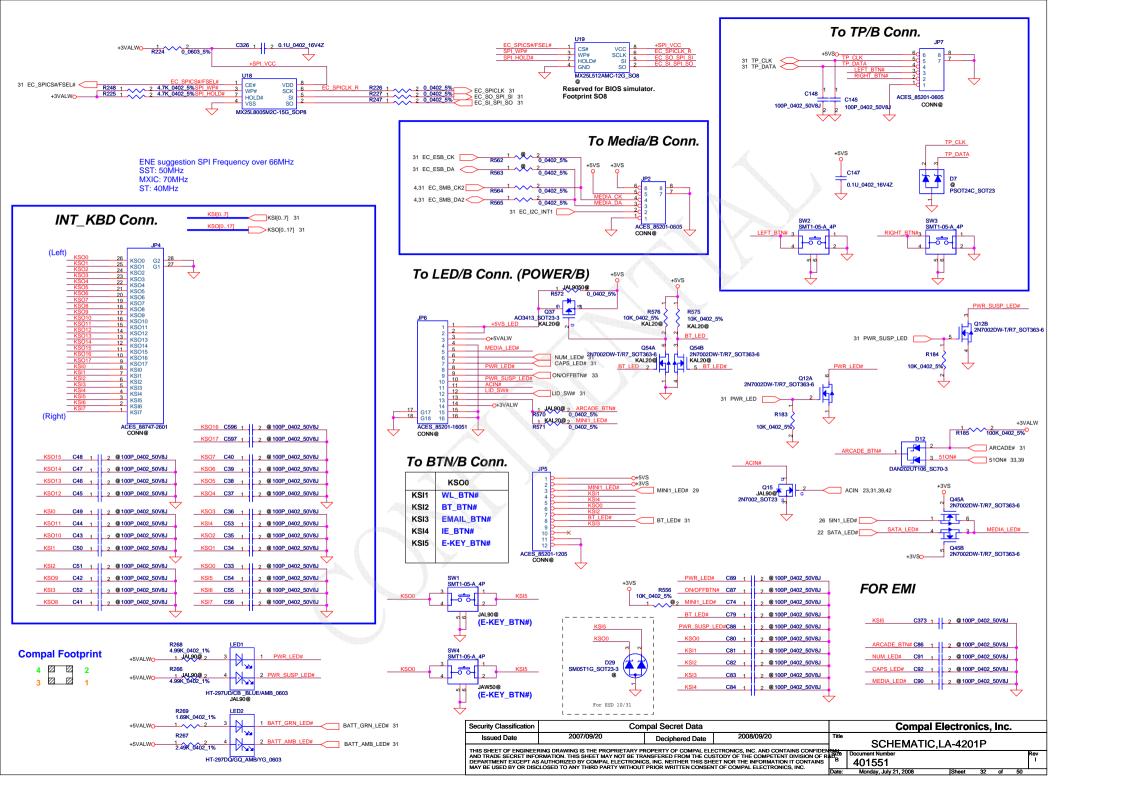
LAN RTL8111C/8102E

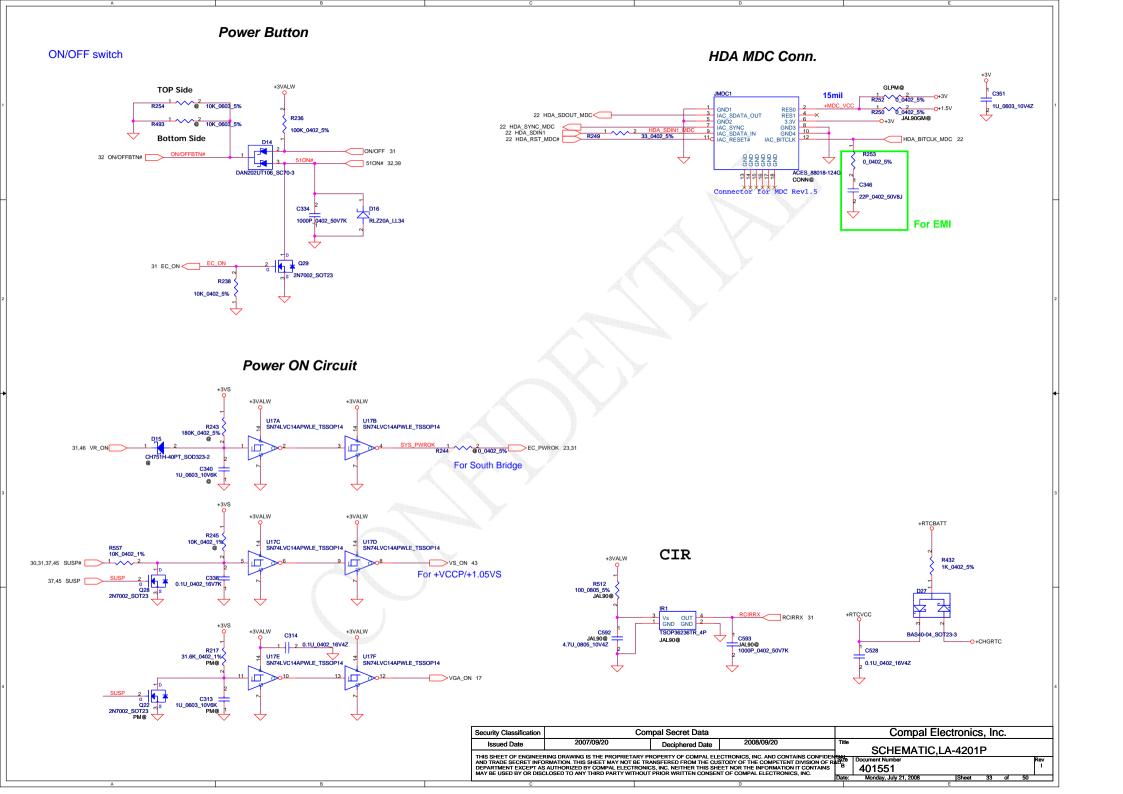


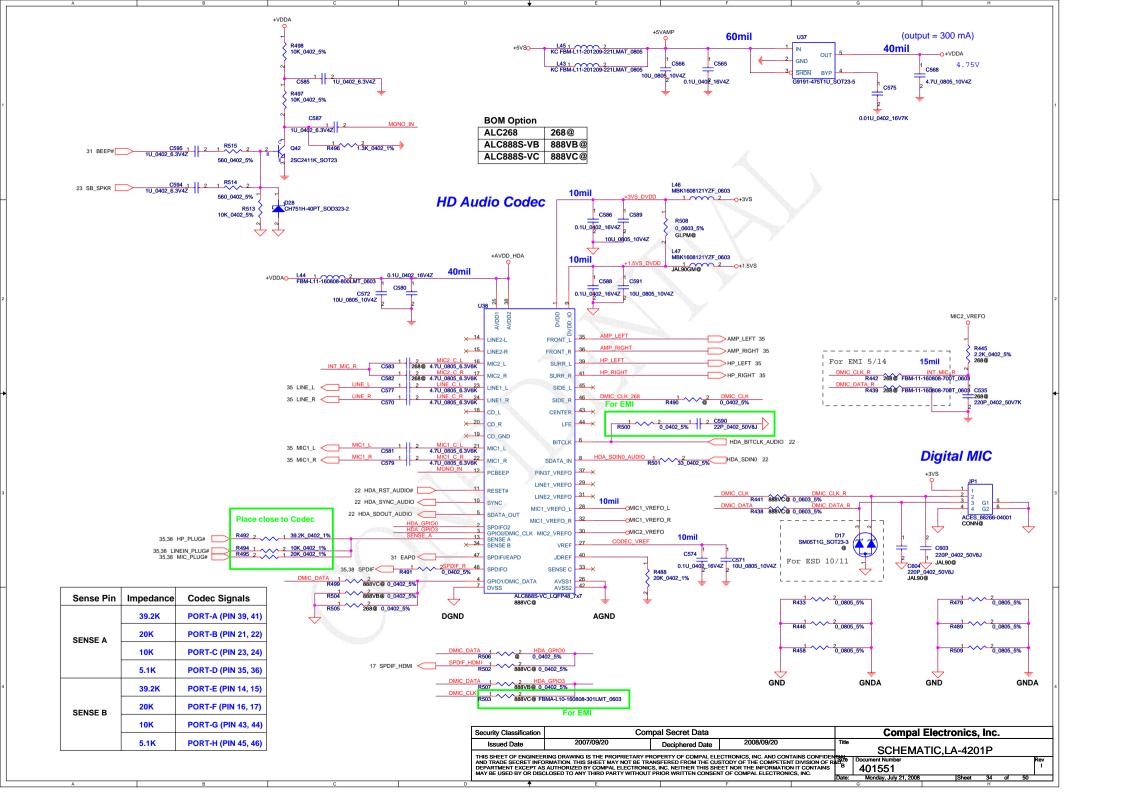


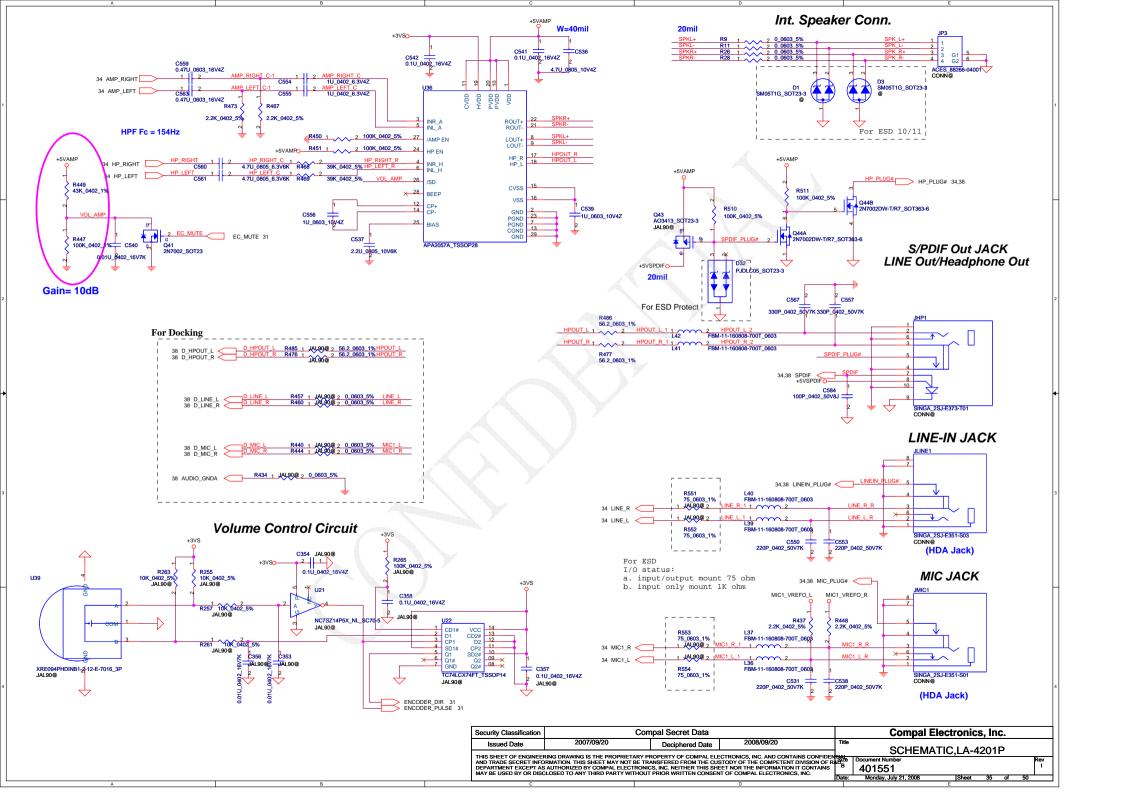
New Card Power Switch New Card Socket (Left/TOP) U14 +3VALW_CARD +3VS_CARD +1.5VS_CARD lmax = 0.275Almax = 1.35AImax = 0.75A 1.5Vin 1.5Vin 1.5Vout 1.5Vout O+1.5VS CARD +1.5VSO 23 LISB20 N1 USB_D-USB_D+ CPUSB# C304 C282 C292 C281 O+3VS CARD 3.3Vin 10U_0805_10V4Z /4Z ABO@ 2 3.3\/out 10U_0805_10V4Z ABO@ 0.1U 0 02 16V4Z 17 AUX_IN -O+3VALW CARD AUX_OUT 16,23,29 ICH_SMBCLK < 16,23,29 ICH_SMBDATA < +1.5VS_CARD C 21 PCI_RST# CPCI_RST# 6 SYSRST# OC# 019 × 31,37,43,44 SYSON PERST# 23,29 ICH_PCIE_WAKE# < +3VALW_CARD WAKE# 31.33.37.45 SUSP# +3 3//VIIA (Internal Pull High to AUXIN) +3VS_CARD GND (Internal Pull High to AUXIN) RCLKEN1 18 CLKBEO# 23 CD DE# 16 CLK_PCIE_CARD# 16 CLK_PCIE_CARD REFCLK-REFCLK+ ABO@ G577NSR91U_TQFN20_4x4 0.1U_0402_16V4Z 23 PCIE_PTX_C_IRX_N1 23 PCIE_PTX_C_IRX_P1 ABO@ PERn0 U16 5 10K 0402 5% 24 25 EXP_CLKREQ# 16 PETp0 +1.5VS ABO@ NC7SZ32P5X_NL_SC70-5 RCLKEN1 2 Q25 2N7002_SOT23 ABO@ GND GND FOX_1CH4110C_LT C310 C283 CONN® 10U_0805_10V4Z ABO@ 10U_0805_10V4Z ABO@ 2 10U_0805_10V4Z USB CONN. (Stack-up Type) Bluetooth Conn. Finger Print Conn. +USB VCCA +USB VCCA +3VALW C523 C187 C217 220U_C6_6.3V_M_R15 @ 150U_D2_6.3VM R577 0_0603_5% C316 ABO@ 0_0603_5% 470P 0402 50V7K 470P_0402_50V7K ABO@ 0.1U_0402_16V4Z 1U_0603_10V4Z ABO@ Q24 AO3413_SOT23-3 31 BT_ON# R222 ABO@ 10K_0402_5% 0.1U_0402_10 2 1 23 USB20_N0 < 23 USB20_P0 < 23 USB20_N2 23 USB20_P2 W=40mils 23 USB20_N10 23 USB20_P10 O+BT VCC GND: GND1 60 GND1 Z GND3 GND2 FO GND3 BO GND4 C308 1 C325 1 ABO@ ABO@ ABO@ 4.7U_0805_10V4Z ACES 85201-04051 CONN@ BO GND4 300_0603_5% ABO@ SUYIN_020173MR004G565ZR SUYIN_020173MR004G565ZR CONN@ CONN@ Q26 2N7002_SOT23 ABO@ +5VALW +USB VCCA R170 0_0402_5% +BT_VCC OUT OUT OUT USB_OC#2 23 GND R171 2 USB OC#0 23 13 CKH C522 23 USB20_P5 < TPS2061DRG4_SO8 10K_0402_5% 23 USB20 N5 4.7U_0805_10V4Z C240 29 WLAN_BT_DATA 29 WLAN_BT_CLK +USB_VCCAC 0.1U_0402_16V4Z X 8 6 GND 29,37,38 SYSON# ACES_87213-0800G CONN@ @ CM1293-04SO SOT23-6 Compal Electronics, Inc. Security Classification Compal Secret Data 2007/09/20 2008/09/20 Issued Date Deciphered Date SCHEMATIC, LA-4201P THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS COMFIDE AND TRADE SECKET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPITENT DIVISION OF DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION TO CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WITHTEN CONSENT OF COMPAL ELECTRONICS, INC. 401551



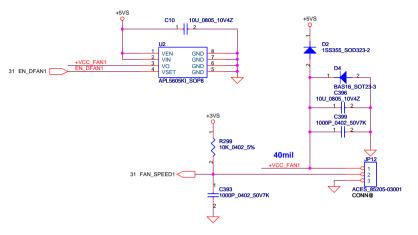




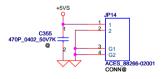


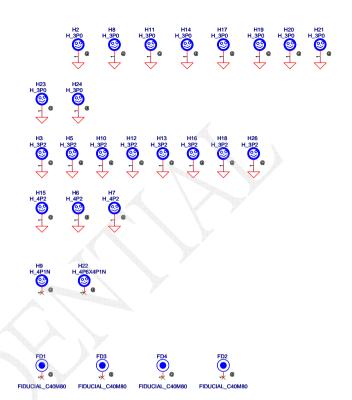


FAN1 Conn

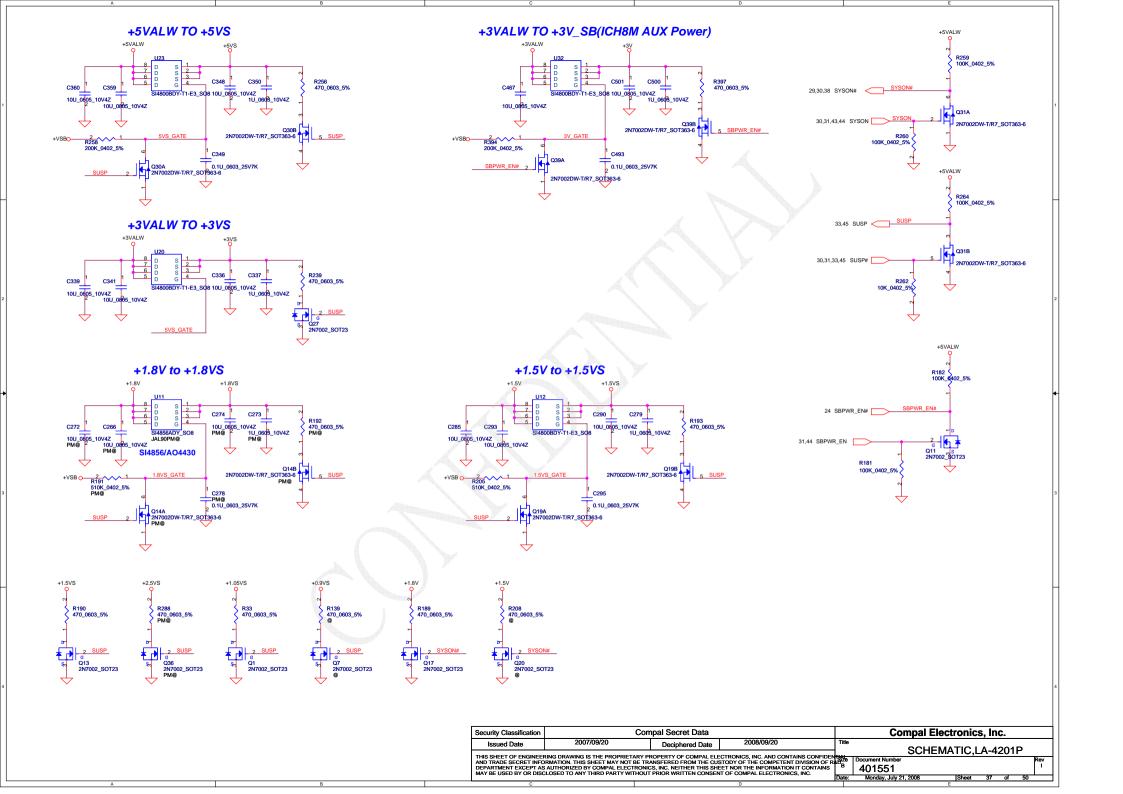


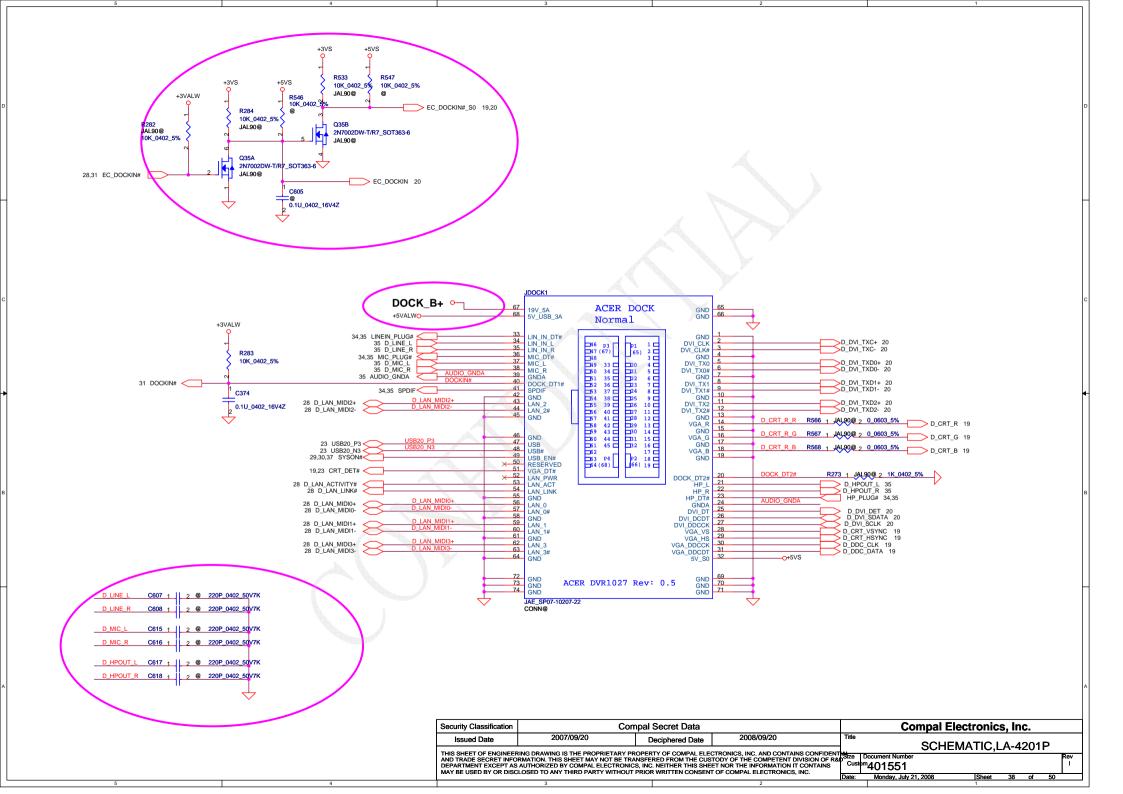
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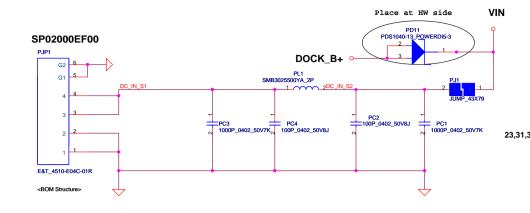


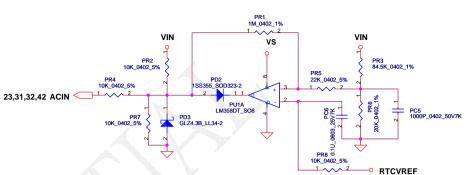


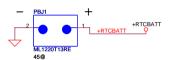
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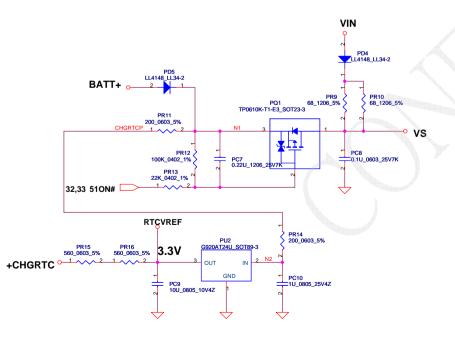


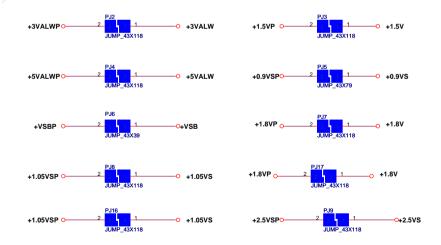
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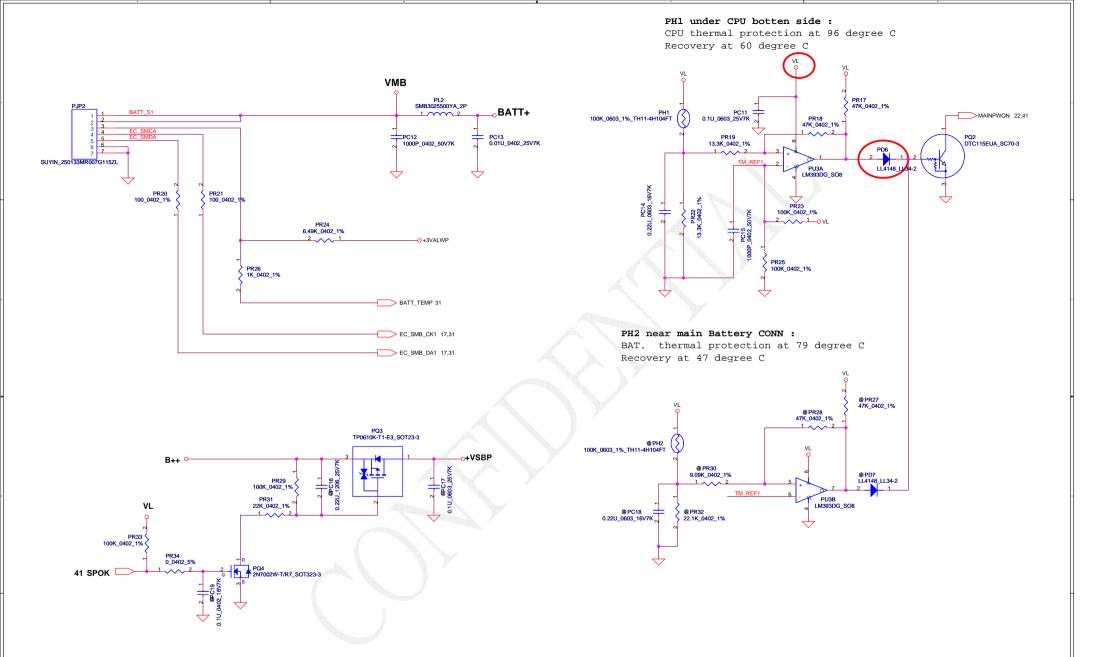
H-->L 16.976V 17.525V 17.728V

L-->H 17.430V 17.901V 18.384V

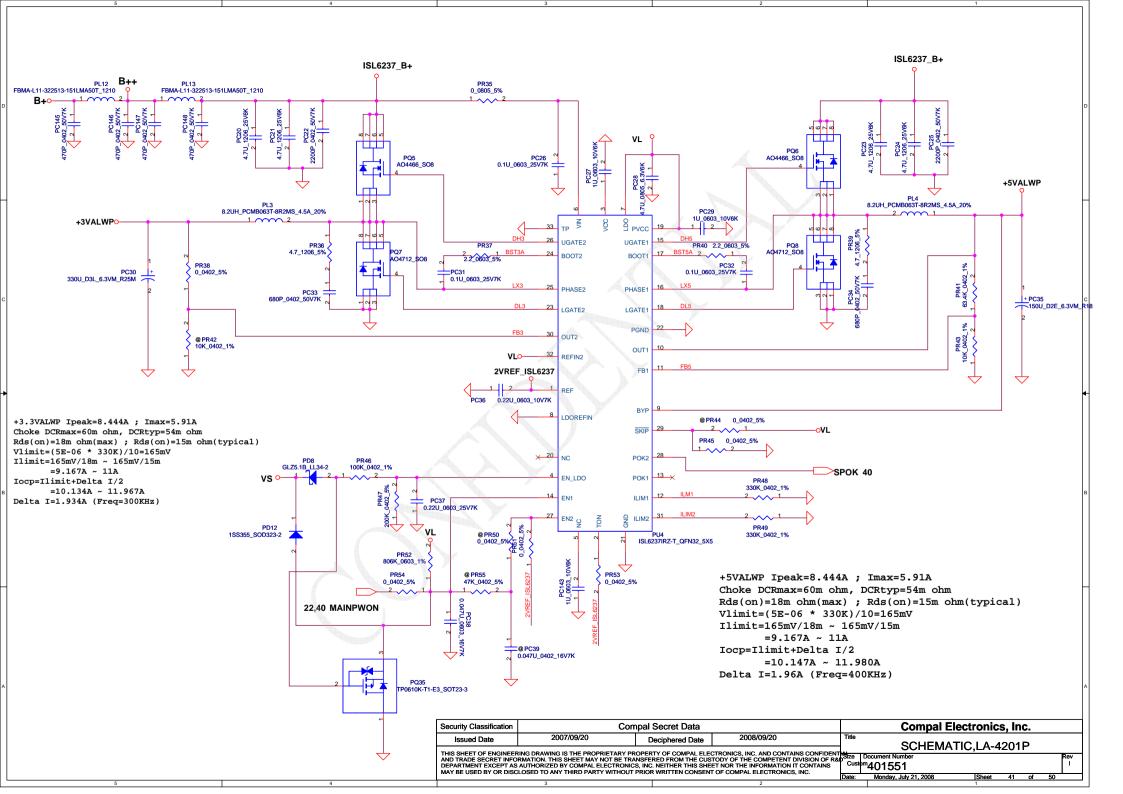


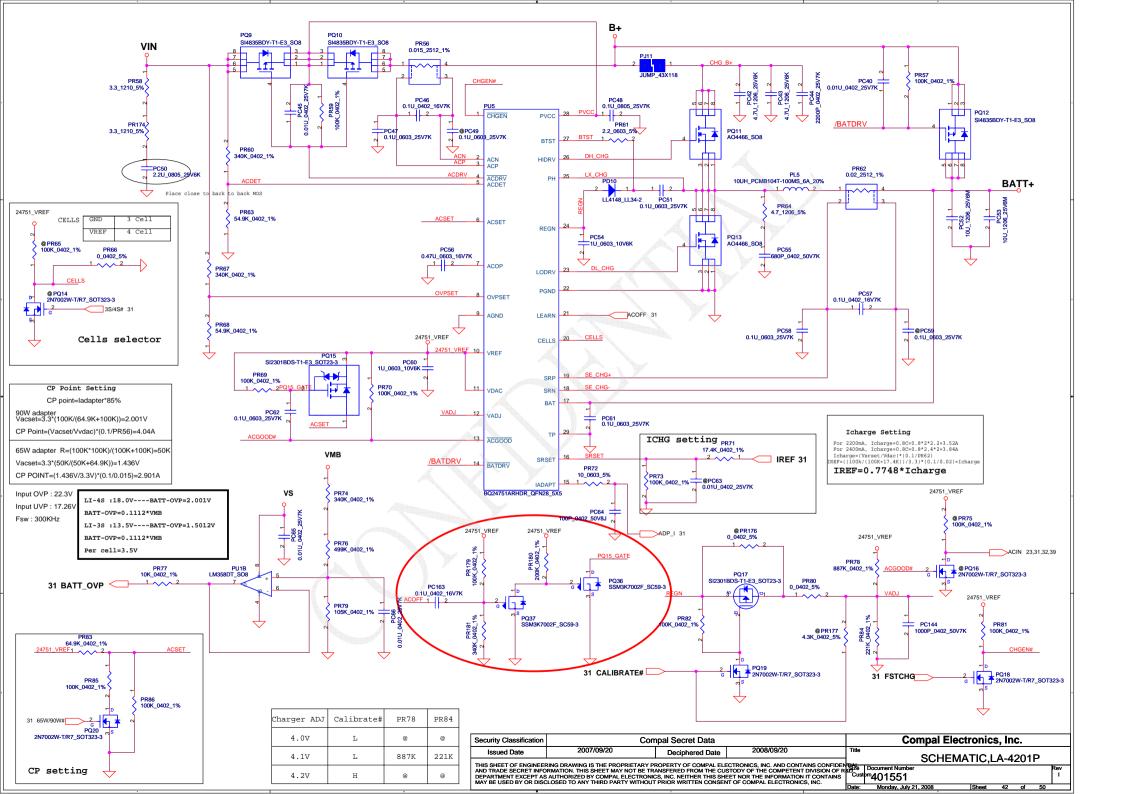


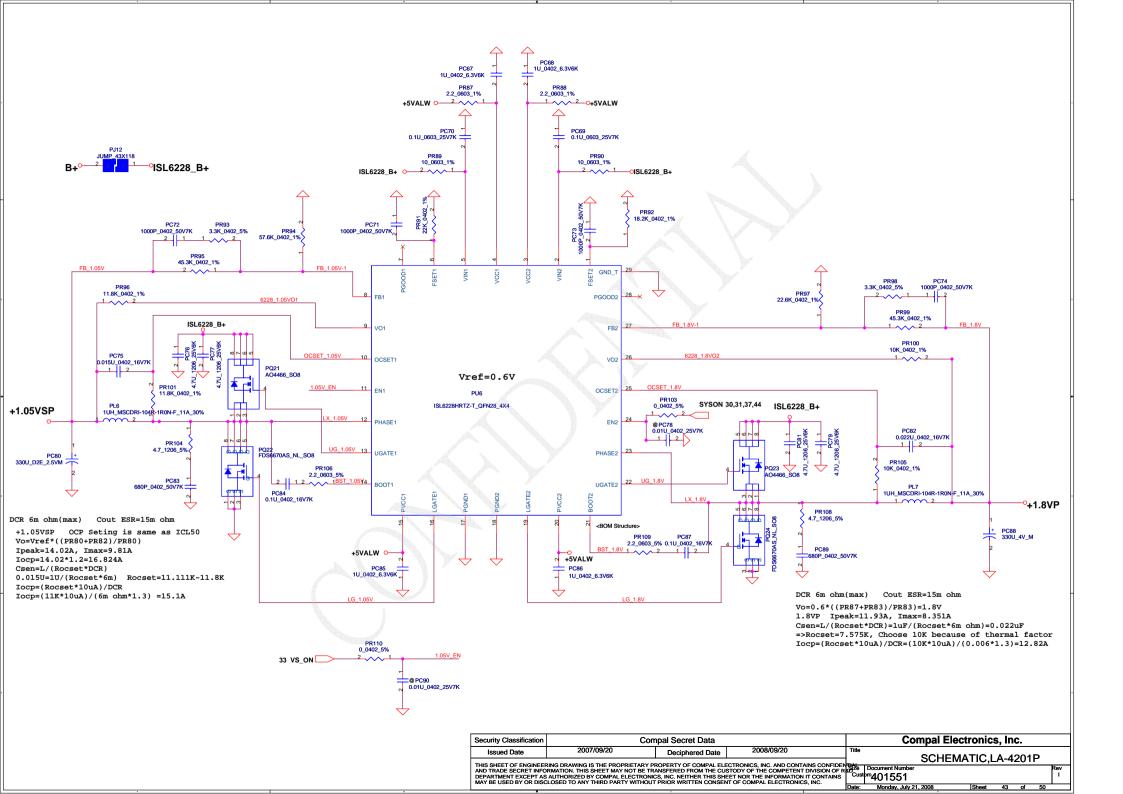
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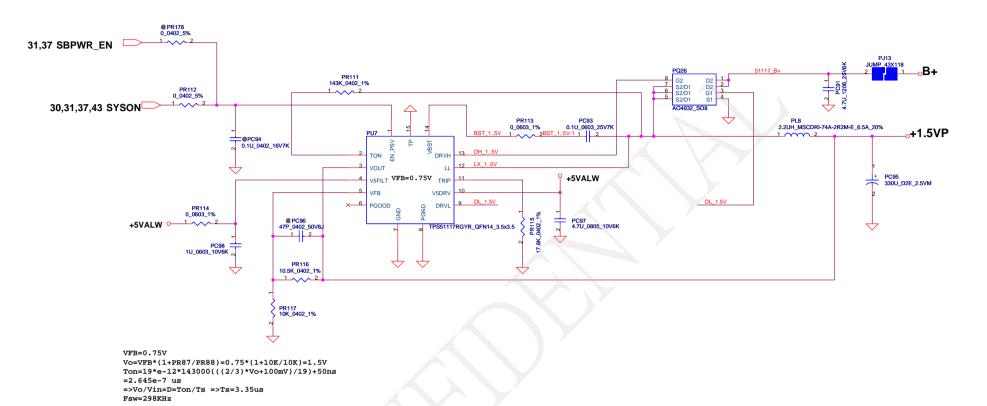


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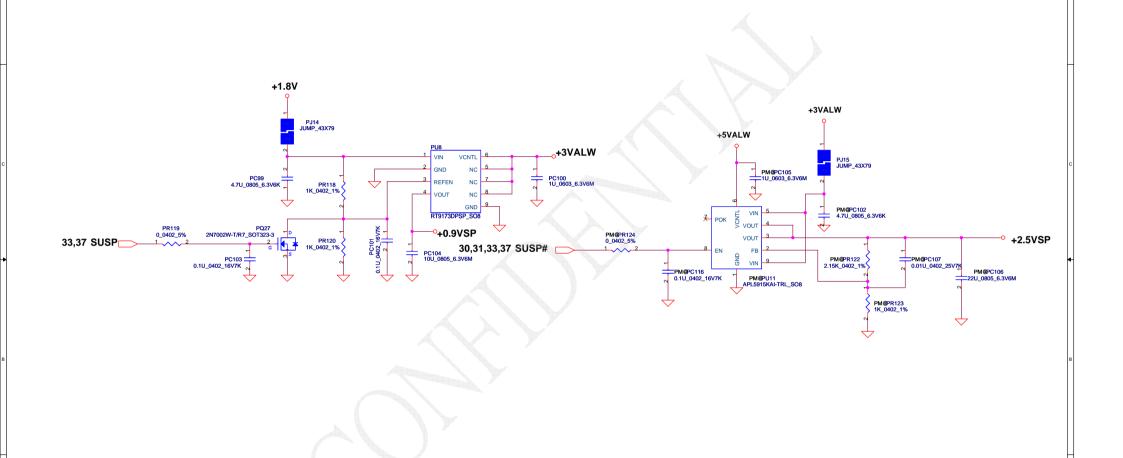




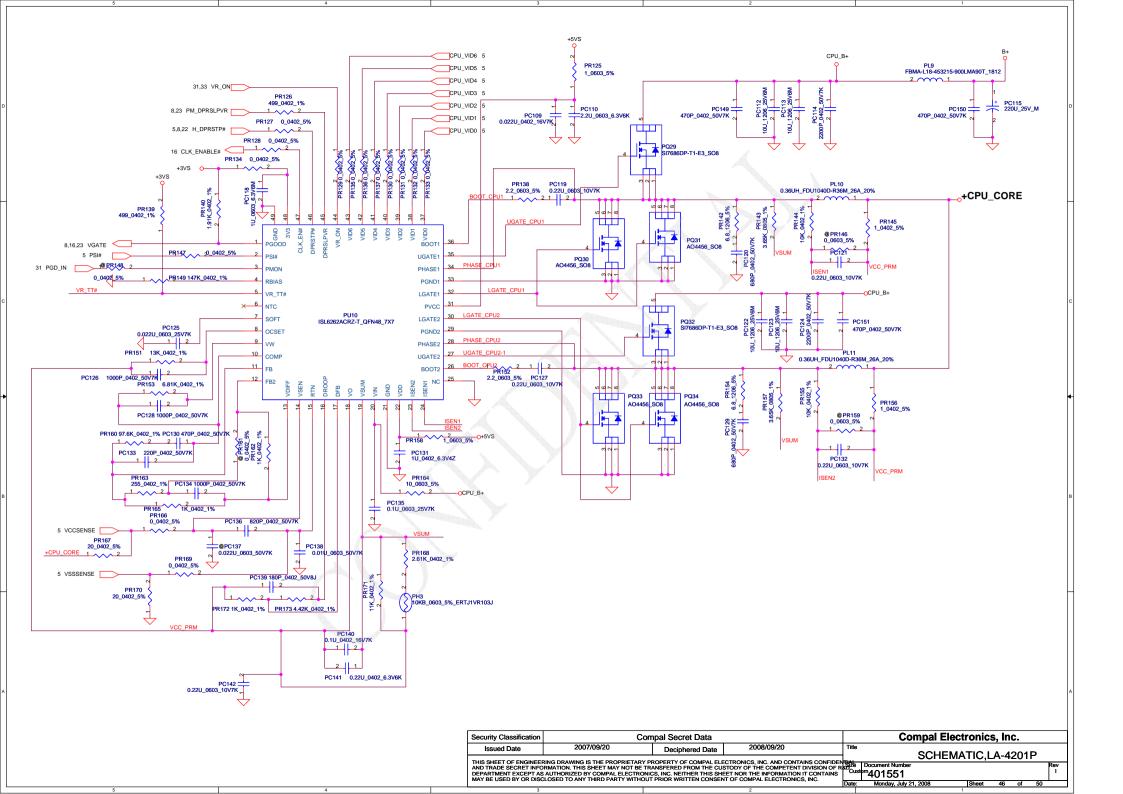


Cout ESR=15m ohm
Ipeak=4.71A, Imax=3.297A, Iocp=5.652A
Delta I=((19-1.5)*(1.5/19))/(L*Fsw)=2.107A
=>1/ZDeltaI=1.053A
Vtrip=Rtrip*1.0uA=17.8K*10uA=0.178V
Iocpmin=Vtrip/Rdsonmax*1.2+1.053A
=0.178/(0.027*1.2)+1.053=5.493A+1.053A=6.546A
Iocpmax=(0.178/(0.021*1.1))+1.053A=7.705A+1.053A
=8.758A
Iocp=6.546A-8.758A

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Version change list (P.I.R. List)

Page 1 of 2 for PWR Date | Phase

1					for PWR		1	
Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	Date	Phase	
1	ISL6237 can't shutdown while battery only.	ISL6237 can't shutdown while battery only.	0.1	41	Add PQ35 SB906100210 TP0610K.	20071031	EVT	
2	Delete PD1	Because we can cost down and B+ has another one.	0.2	39	Delete PD1 SCSB540C080 (S SCH DIO B540C-13-F SMC)	20071115	DVT	
3	3/5V exit on battery mode shutdown.		0.3	41	Add SC100001K00 (S DIO 1SS355 SOD323 T/R-5K	20071211	DVT	
4	PD11 has over temp. issue.	Because PD11 has over temperature issue in JAQ60, we change it to a 10A diode.	0.3	39	Change PD11 from SCSB540C080 to SCS00002F00 .	20071211	DVT	
5	Add snubber in 3/5V by EMI request.	Add snubber in 3/5V by EMI request.	0.3	41	Add PR36 and PR39 to SD001470B80	20071211	DVT	
6	Down size.	Down size. by sourcer request.	0.3	46	Change PC136 from SE025821K80 to SE000003W00	20071211	DVT	
7	Down size.	Down size. by sourcer request.	0.3	46	Change PC120 and PC129 from SE024681J80 to SE074681K80	20071211	DVT	
8	Down size.	Down size. by sourcer request.	0.3	43	Change PC72 and PC74 from SE068102J80 to SE074102K80	20071211	DVT	
9	2nd source trial run TI controller.	2nd source trial run TI controller.	0.3	41	Add PC143 SE080105K80	20071211	DVT	
10	Add snubber in 3/5V by EMI request.	Add snubber in 3/5V by EMI request.	0.3	41	Add PC33 and PC34 SE074681K80	20071211	DVT	
11	To meet Jeta SPEC.	To meet Jeta SPEC.	0.3	42	Add PC144 SE074102K80	20071211	DVT	
12	Increase +5VALWP	HW requirement.	0.4	41	Change PR41 from SD034619280(S RES 1/16W 61.9K 0402 1%) to SD03463K280(S RES 1/16W 63.4K 0402 1%)	20080123	PVT	
13	Increase +5VALWP	HW requirement.	0.4	43	change PR94 from SD034604280(S RES 1/16W 60.4K 0402 1%) to SD034576280(S RES 1/16W 57.6K 0402 1%)	20080123	PVT	
14	Increase +5VALWP	HW requirement.	0.4		Change PRI16 from SD034100280(S RES 1716W 10K 0402 1%) to SD034105280(S RES 1/16W 10.5K 0402 1%)	20080123	PVT	
15	Add EMI solution.	For EMI requirement.	0.4	41,42,	Change PR37, PR40, PR61, PR106, PR109, PR138, PR152 from SD013000080(S RES 1/10W 0 +-5% 0603) to SD013220B80 (S RES 1/10W 2.2 +-5% 0603)	20080123	PVT	
16	Add EMI solution.	For EMI requirement.	0.4	43	Add PR64, PRI04 and PRI08 SD001470B80(S RES 1/4W 4.7 +5% 1206)	20080123	PVT	
17	Add EMI solution.	For EMI requirement.	0.4	43	Add PC55, PC83 and PC89 SE074681K80(S CER CAP 680P 50V K X7R 0402)	20080123	PVT	
18	Add EMI solution.	For EMI requirement.	0.4	41	Add PC145, PC146, PC147, PC148 SE074471K80 (S CER CAP 470P 50V K X7R 0402)	20080123	PVT	
19	Add EMI solution.	For EMI requirement.	0.4	41	Add PL12, PL13 SM010016410 (S SUPPRE_KC FBMA- L11-322513-151LMA50T)	20080123	PVT	
20	AO4916 will be EOL.	AO4916 will be EOL.	0.5	44	Change PQ26 from SB000002W80 S TR A04916 2N S08 to SB0000BG00 S TR A04932_S08	20080201	PVT	
21	Thermal shutdown issue.	Change OTP setting from 92C to 96C.	0.6	40	Change PR19 and PR22 to SD034133280(S RES 13.3K 0402 1%)	20080214	PVT	
22	EMI request.	EMI request.	0.6	46	Add PC149,PC150,PC151 SE074471K80(S CER CAP 470F X7R 0402)	20080214	PVT	
23			- +			1		
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11/28-A --> B Change List Page 12, Mount R83, C179, C188 Change R91 BOM structure to @ Page 19, Mount D21, D22, D23 Page 20, Change U40, U41 BOM structure to @ Page 19, Change C430, C422, C406 with BOM structure GM@ Page 20, Add R548, R549 2.2K_0402 with BOM structure @ Change R542, R543 BOM structure to PM@ Change Q3, Q5, Q46, Q47 to BSH111 Page 28. Change T1 to SP050003T10 Page 34, Change C603, C604 location and BOM structure to JAL90@ Page 35, Change R449 to 43K 0402 1% Page 27, Add R550 with BOM structure @ 11/19-Page 49, Add option component for C430, C422, C402, C429, C421, C405 Rev A Del C419, C428, C432, C513, C214 (Option Component) Page 19, Add R544, R545 0 0402 with BOM structure JAL90@ Page 20, Add U40, U41 SN74CBTD3306CPWR TSSOP8 with BOM structure JAL90@ Page 35, Change R486, R477, R485, R476 to 56.2 0603 1% Mount R342 Page 38, Add R546, R547 10, 0402, 5% with BOM structure @ Update MCH and ICH part number. U31 --> SA00001ZO30 (PM) SA00001P930 (GM) U9 --> SA00002AN10 (ICH9) 12/07-Page 12, Add C606, 220U D2 4VM R15 with BOM Structure GM@ 11/14-Change C435 to 220uF D2 with BOM Structure @ Rev B Page 17, Update JMXM1 PCBfoot to QUASA CA0481-230N00 230P-T Page 20, Add R542, R543 4.7K 0402 with BOM Structure JAL90@ **Update Power Schematics** 12/06-Page 4, Add R541 10K 0402 with BOM Structure @ Page 17, Add R534 0 0402 with BOM Structure PM@ Change D30, R516 BOM Structure to @ Page 31, Add R540 100K 0402 with BOM structure JAW50@ Change R186 BOM Structure JAL90@ Page 38, Add R533 10K_0402 with BOM Structure JAL90@ Add C605 0.1U 0402 with BOM Strcture @ Change Q35 to 2N7002DW-T/R7 SOT363-6 Page 16, Update U15 to ICS9LPRS387BKLFT (SA000020H10) Page 31, Delete R534 Page 34. Delete R533 Page 38, Update JDOCK1 CIS Symbol to JAE_SP07-10207-19_68P-T 12/04--Page 16, 17, 19 Delete Q23, Q37, Q38 2N7002DW-T/R7 SOT363-6 Add Q48, Q49, Q50, Q51, Q52, Q53 2N7002_SOT23 Page 22, Add 10K 0402 with BOM Structure JAW50@ Change R61 BOM Structure to JAL90@ Page 31, Change R215 to 8.2K 0402 Page 34, Add C603, C604 220P 0402 50V8J with BOM structure @ Page 18, C368 change to 680P 0402 50V7K Page 20, D20 Change to CH751H-40PT SOD323-2 Delete Q4 Add Q46, Q47 2N7002 SOT23 with BOM Structure JAL90@ Page 26, Delete R532, Q46 Add R538, R539 0 0402 with BOM Structure @ Change D31 with BOm Structure @ Change U34 PN to SA00001W910 Page 31 Change EC SMB CK2/DA2 Pull High to +3VS Page 32. Add SW4 with BOM Structure JAW50@ Change SW1 BOM Structure to JAL90@ Change JP2 Pin3/Pin4 to EC SMB CK2/DA2

Page 12, Add R536, R537 0 0402 with BOM Structure PM@ Page 30, Change U14 to G577NSR91U Page 34, Change R438, R439, R441, R442 to 0, 0603 (BOM Error) Page 35, Change R473, R467 to 2.2K 0402 5% Change R9, R11, R26, R28 to 0 0603 (BOM Error) Page 19, Change D5 to RB491D_SC59-3 accordig to Module design Page 25, Update JSATA2(HDD) PCB footprint to OCTEK_SAT-22SU1G_22P_NR-T Page 33, C313 change to 1U 0402 6.3V6K Page 37. Mount R189. Q17 for +1.8V dischange circuit. Page 26, Add R535 22 0402 Page 31, Add R534 0_0402 for +RTCVCC Page 8, R482, R480 Pull down (CLK_DREF_96M#/CLK_DREF_SSC#) Page 12, L32, L10, C505, C513, C263, C214 BOM Structure change to GM@ Add C513, C214 0 0402 (PM@) for Option Component (Page 49) Page 23, Unmount R341 Page 28, Update R521, R522, R523, R524, R525, R526, R527, R528, R529, R530 function field. Page 29, SWAP function of JMINI1 and JMINI2 (JMINI1 for Robson2, JMINI2 for WLAN) Delete C355 0.1U 0402 Add R531 0 0402 Page 34, Add R533 0 0402 for ALC888VB DMIC CLK Page 7, 8, 9, 10, 11, 12, 13 change U31 BOM Structure from GM@ to JAL90GM@ Page 8, R102 BOM Structure change from GM@ to JAL90GM@ Page 10, C210, C218, C222, C228, C208, C215, C220, C223 add BOM Structure PM@ Page 49, Add C210, C218, C222, C228, C208, C215, C220, C223 option component BOM Structure JAL90GM@ Add U31 Cantiga-GL, LED1 with BOM Structure JAW50@ Page 12, R396, C498 BOM Structure change from GM@ to JAL90GM@ R395 BOM Structure change from PM@ to GLPM@. Page 17, R331, R333 BOM Structure change from GM@ to JAL90GM@ Page 19, R322, R327, R329 BOM Structure change from GM@ to JAL90GM@ U28 add BOM Structure JAL90@ Add R518, R519, R520 0_0402_5% for JAW50 CRT signal Page 20, R51, R52, Q4, R344, R336, C439, C440, R332, U30, R67, R72, Q3, Q5, D6, F2, C443, R351, R354, R358, R364, R365, R367, R372, R373, D19, C427, C431, U27, D20, R305, R306, 307, R308, R309, R310 add BOM Structure JAL90@ Page 22, R408, R409, R410, R411 change BOM Structure from GM@ to JAL90GM@ Page 23, R38, R53, R40, R54, R55, R34, U5 change BOM Structure from GM@ to JAL90GM@ Page 24, R160, R162 BOM Structure change from PM@ to GLPM@ R159, R161 BOM Structure change from GM@ to GLPM@ Page 28, Add R521, R522, R523, R524, R525, R526, R527, R528, R529, R530 0 0402 5% for JAW50 U1 add BOM Structure JAL90@ Page 29, C343, C352, C342, C344, C312, C355 add BOM Structure JAL90@ Page 32, Q15, LED1 add BOM Structure JAL90@ Page 33, R512, C592, IR1, C593 add BOM Structure JAL90@ R252 change BOM Structure from PM@ to GLPM@ R250 change BOM Structure from GM@ to JAL90GM@ Page 34, C583, C582, R445, C535, R442,R439 change BOM Structure from @ to 268@ R490, R506 change BOM Structure from 268@ to @ R441, R438 add BOM Structure 888VC@ Page 35, R485, R476, R457, R460, R440, R444, R434, U39, R263, R255, R257, R261, C356, C353, C354, U21, R265, C358, U22, C357, Q43 add BOM Structure JAL90@ Page 37, C272, C266, U11, C274, C273, R192, Q14, C278, R191 add BOM Structure PM@ Page 38, R282, R284, Q35, R273 add BOM Structure JAL90@ Page 37, Change R262 from 100K 0402 to 10K 0402 for Power Require(for 2.5V LDO).

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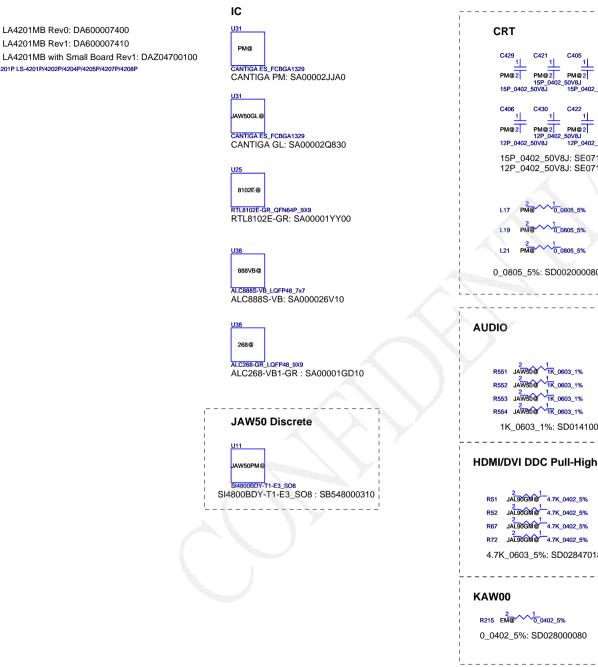
B --> C Change List Page 6, Change C98 BOM structure to @ 0218----Page 20, Add R569 with BOM structure @ Page 23, R34, R38, R40, R53, R54, R55 change BOM structure to @ Page 31, Change R215 to 18K **Update Power Schematics** 0213---Page 11, Delete R113 Add J1 JUMP 43X79 with BOM structure @ Page 31, R558, R559 0 ohm with BOM structure @ R560, R561 4.7K with BOM structure @ Page 32, R562, R563 0 ohm with BOM Structure @ R564, R565 0 ohm Page 38. Delete C619 Add R566, R567, R568 0 0603 with BOM Structure JAL90@ Page 12, Change L31 to MBK1608301YZF 0603 with BOM structure GM@ Change R163 to 0 0805 5% Page 23, Change BOM Structure of U5 to @ Page 27, Change BOM Structure of R555 and R550 to @ Page 33. Change R217 to 31.6K 0402 1% Change C313 to 1U 0603 10V6K Page 34, Change R503 to FBMA-L10-160808-301LMT_0603 01/31---Page 23. Delete U10 01/29-Page 23, Change R152 BOM Structure to @ Page 4, Change U8 to SA00001Z700 (EMC1402) Page 33, Change C338 to SE076104K80 Page 35, Mount C584 01/23-Page 38 Delete F3, R558~560, C609~614 Page 11. Delete R79 Change J1 Symbol to JUMP 43X79 Page 33, Add R557 10K (Check) Change R245 BOM Structure with @ Page 38, Add C609~614, R558~560 (Check) C607,608, 615~619 (Check) 01/17--Page 11, Add R79 0 0805 **Update Power Schematics** 01/16--Page 11, Delete R79 0 0805 Add J1 JUMP 43X79 Page 16, Change C296, R301 to 27P_0402 Page 19, Change L17, L19, L21 BOM structure to GM@ Page 23, Mount U29, R339 Add U10 with BOM structure @ (Co-lay with U5) Change R340 Bom structure to @ Change U5 to MX25L4005AMC-12G SO8 (SA00002A900) Page 27, Change U26, C420 BOM structure to @ Change R550 to 0 0402 Add R555 0 0402 Page 32, Change R269 to 240 0402 5%, R267 to 453 0402 1% Change R268 pin1 connect to +5VALW Page 33, Change R217 to 18K 0402 1% with BOM structure PM@ Page 35, Add R551,R552, R553, R554 75_0603_1% with BOM structure JAL90@ Add D32 PJDLC05 SOT23-3 Page 38, Add F3 3A_15VDC_SMD2920P300TF/15 Page 49, Add R551,R552, R553, R554 1K_0603_1% with BOM structure 268@ Add L17, L19, L21 0 0805 with BOM structure PM@ Update U38 (ALC268-VB1-GR) PN:SA00001GD10 for JAW50

C	> C2 Change List
031	9
Pad	ge 20, Add R574 0 ohm with BOM Structure JAL90@
•	ge 32, Add R570 0 ohm with BOM Structure JAL9050@
	d R571 0 ohm with BOM Structure KAL20@
	d Q37 AO3413 with BOM Structure KAL20@
	d R575, R576 10K with BOM Structure KAL20@
	d Q54 2N7002DW with BOM Structure KAL20@
	date Power Schematics
	date U31 PN to SA00002JT50(GM)/SA00002JJ50(PM)
Op.	adia do i i i de diadoca i do (elliperiodoca) i lip
C	2> PreMP Change List
)4
	ge 20, Change R51, R52, R67, R72, R542, R543, R574 BOM structure to JAL90PM@
	ge 37, Change U11 BOM structure to JAL90PM@ ge 50, Add U11 SI4800BDY-T1-E3_SO8 withe BOM structure JAW50PM@
	ange U31 BOM Structure to JAW50GL@
	24
	ge 37, Change U12, U20, U23, U32 to SI4800BDY
	0 ge 23, Change R388 BOM structure to EM@
•	ge 23, Change K366 BOW Structure to EM® 18
	d ABO@ for Bluetooth/NewCard/CardReader option
	22, C316, C317, C332, Q24, C308, C325, R235, Q26
	4, U16, Q25, C310, C298, C283, C307, C292, C294, C304, C303, C281, C282, R220, C487, C480
	24, C525, C526, C527, C529, C530, C532, C533, C534, C543, C544, C545, C546, C544, C545
	47, C548, C549, D26, R427, R428, R429, R430, R435, R436, R443, R452, R453, R535, U34
	ge 23, Change R417 BOM structure to EM@
	lange R416 BOM Sturcture to ABO@
	ge 31, Change R215 BOM structure to ABO@
	ge 32, Change R570 BOM structure to ABO@
	ge 50, Add R215 with BOM structure EM@
	9-30, Add K213 with BOW Structure EM®
	ge 4, Mount R541
	ge 32, Change R266, R268 Bom Structure to JAL90@
	ge 50, Add R266 2.49K_0402_1% with BOM Structure JAW50@
	d R268 1.69K 0402 1% with BOM Structure JAW50@
	lange JAW50 U31 PN to SA00002Q830
	4(For JAW50 Analog MIC, EMI Requirement)
	ge 34 change R439, R442 to FBMA-L11-160808-700LMT(SM010004010) with BOM structure 268@
	3(For Acer Lab P193WAx DVI Detect)
	ge 20, Change R51, R52, R67 and R72 BOM structure to PM@
	ge 50, Add R51, R52, R67 and R72 4.7K_0402 with BOM Structure JAL90GM@
	29(For PC Beep sound, volume down)
	ge 34, Change R496 to 1.3K
	12
	date U9 PN to SA00002JH70
	date U31 PN to SA00002JJA0/SA00002JTB0
	0
	ge 30, Add R577 0_0603 with BOM structure @
	d R578 0_0603
	7
	ge 20, change R574 BOM structure to PM@
	ge 31, change R550, R555, R561 BOM structure to JAL90GM@
	lange R215 to 33K
	ge 32, change R266,R268 to 4.99K 1%
	ange R267 to 2.49K 1%
	ange R269 to 1.69K 1%
Pag	ge 50, change JAL90 PCB P/N to DAZ04700100

C --> C2 Change List

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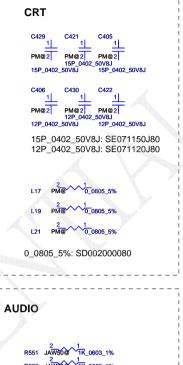


PCB

LA4201MB Rev0: DA600007400

LA4201MB Rev1: DA600007410

PCB JAL90 LA-4201P LS-4201P/4202P/4204P/4205P/4207P/4208P



R553 JAW50@ 1K 0603 1%

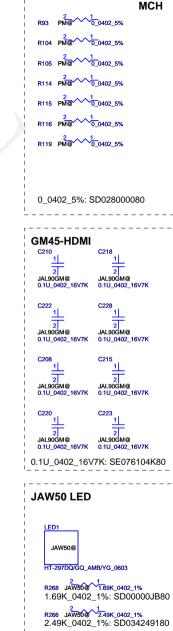
R554 JAW50@ 1K_0603_1%

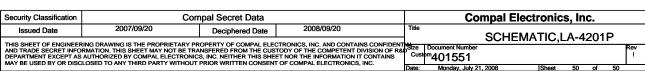
1K_0603_1%: SD014100180

JAL90GM@ 4.7K_0402_5% JAL90GM@ 4.7K_0402_5%

JAL90GM@ 4.7K_0402_5% JAL90GM@ 4.7K_0402_5%

4.7K_0603_5%: SD028470180





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